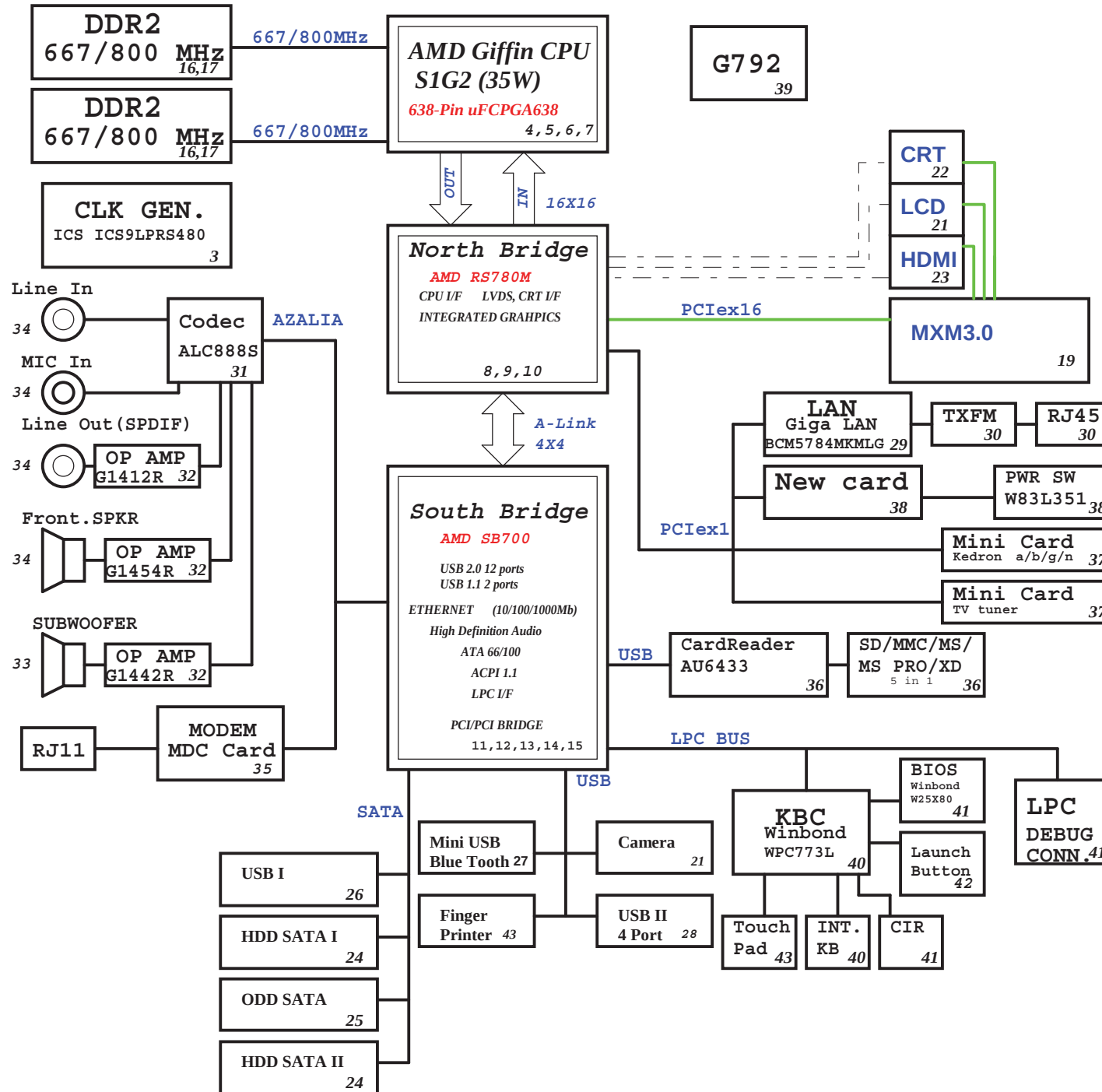


JM70-PU (AS 17") Block Diagram

Project code: 91.4CE01.001
PCB P/N : 48.4CE01.0SC
REVISION : 08255-SC



PCB STACKUP

TOP _____

VCC _____

S _____

S _____

GND _____

BOTTOM _____

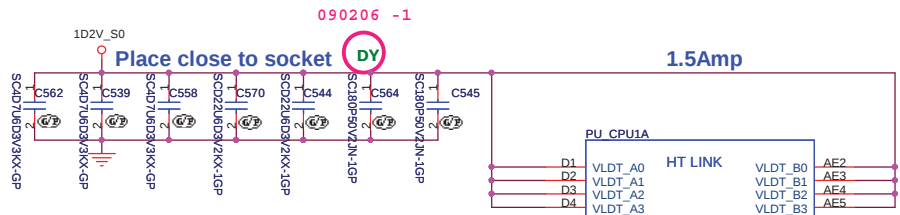
SYSTEM DC/DC TPS51125 49	
INPUTS	OUTPUTS
DCBATOUT	5V_S5 (7A)
	3D3V_S5 (7A)
SYSTEM DC/DC TPS51124 50	
INPUTS	OUTPUTS
DCBATOUT	1D1V_S0 (8A)
	1D2V_S0 (5A)
SYSTEM DC/DC TPS51117 52	
INPUTS	OUTPUTS
DCBATOUT	1D8V_S3 (10A)
RT9026PFP 51	
1D8V_S3	DDR_VREF_S3
	0D9V_S3 (1A)
RT9166 51	
3D3V_S0	2D5V_S0 (300mA)
G957 51	
3D3V_S0	1D5V_S0 (1A)
G9161 (UMA) 51	
3D3V_S5	1D2V_S5 (400mA)
G9131 (DIS) 51	
3D3V_S5	1D2V_S5 (300mA)
CHARGER MAX8731A 53	
INPUTS	OUTPUTS
DCBATOUT	CHG_PWR
	18V 6.0A
	UP+5V
	5V 100mA
CPU DC/DC ISL6265HR 48	
INPUTS	OUTPUTS
DCBATOUT	VCC_CORE_S0_0
	0~1.55V 18A
	VCC_CORE_S0_1
	0~1.55V 18A
	VDDNB
	0~1.55V 18A

<Core Design>

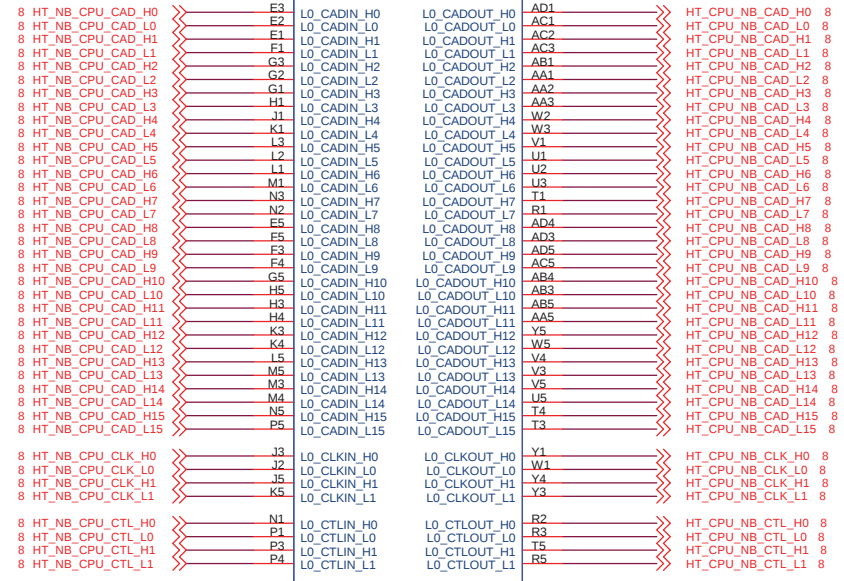
	5	4	3	2	1
D					
C					
B					
A					

<Core Design>

緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
HISTORY			
Size	Document Number		Rev
A3	JM70-PU		-2
Date:	Monday, March 02, 2009		Sheet 2 of 56



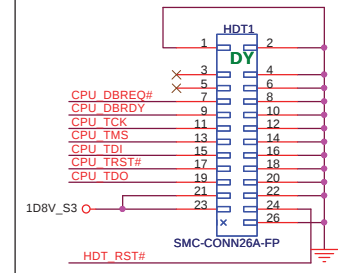
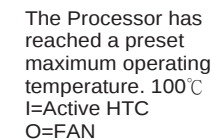
State	Specification	Notes	ZM200100M2303
S0.C0.Px	Tcase Max	3	TBD
	NB COF	1	400 MHz
	VID_VDDNB Min	2	0.950 V
	VID_VDDNB Max	2	0.950 V
	Startup P-state		S0.C0.P7
S0.C0.P0	CPU COF	1	2000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	IDD Max	3	TBD
S0.C0.P1	CPU COF	1	1800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1500 MHz
S0.C0.P2	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1300 MHz
	TDP	3	TBD
S0.C0.P3	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
S0.C0.P4	VID_VDD Max	2	1.125 V
	CPU COF	1	800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
S0.C0.P5	CPU COF	1	500 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
S0.C0.P6	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
	TDP	3	TBD
S0.C0.P7	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V

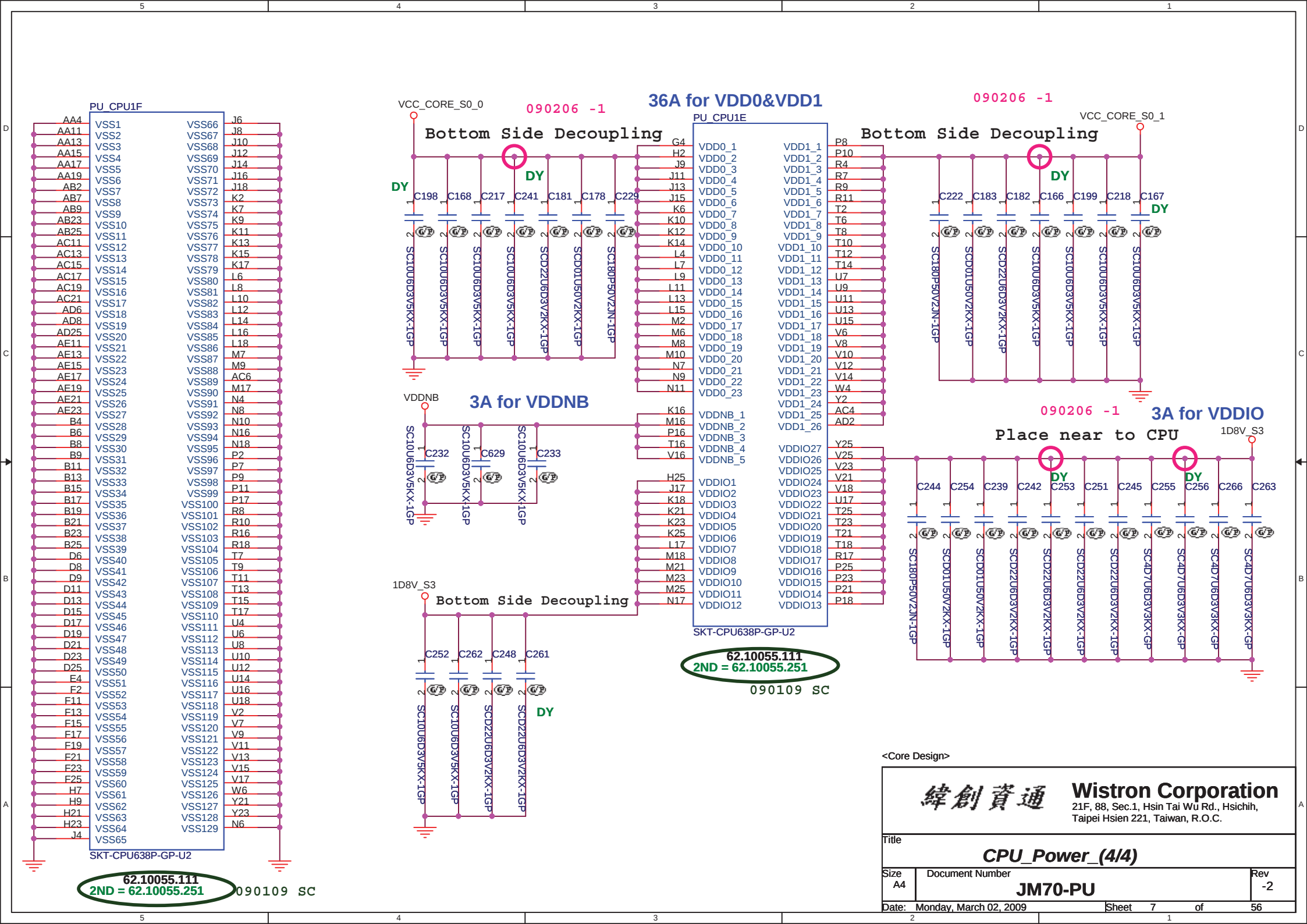


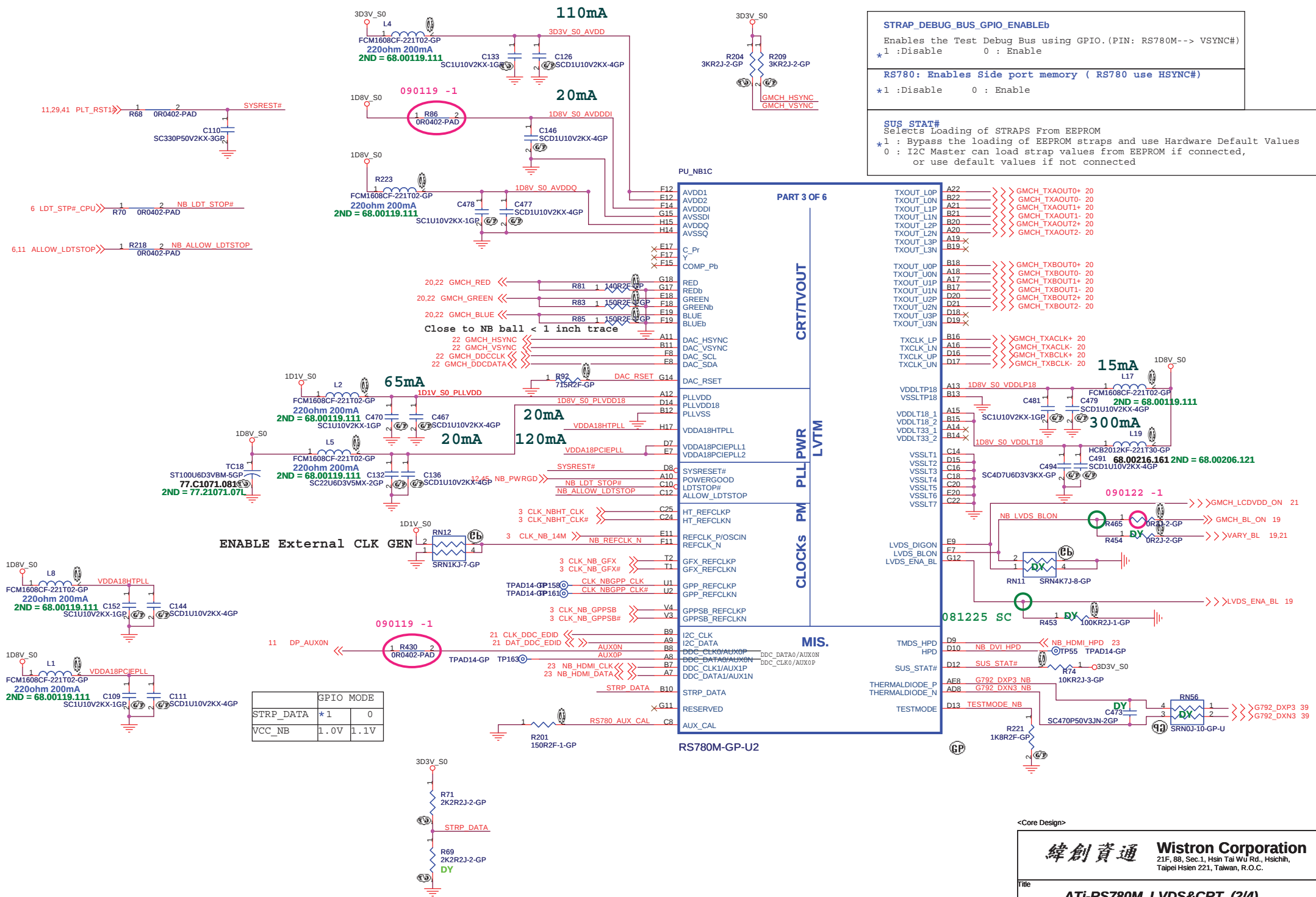
SKT-CPU638P-GP-U2

62.10055.111
ZND = 62.10055.251

090109 SC
SKT-BGA638H176



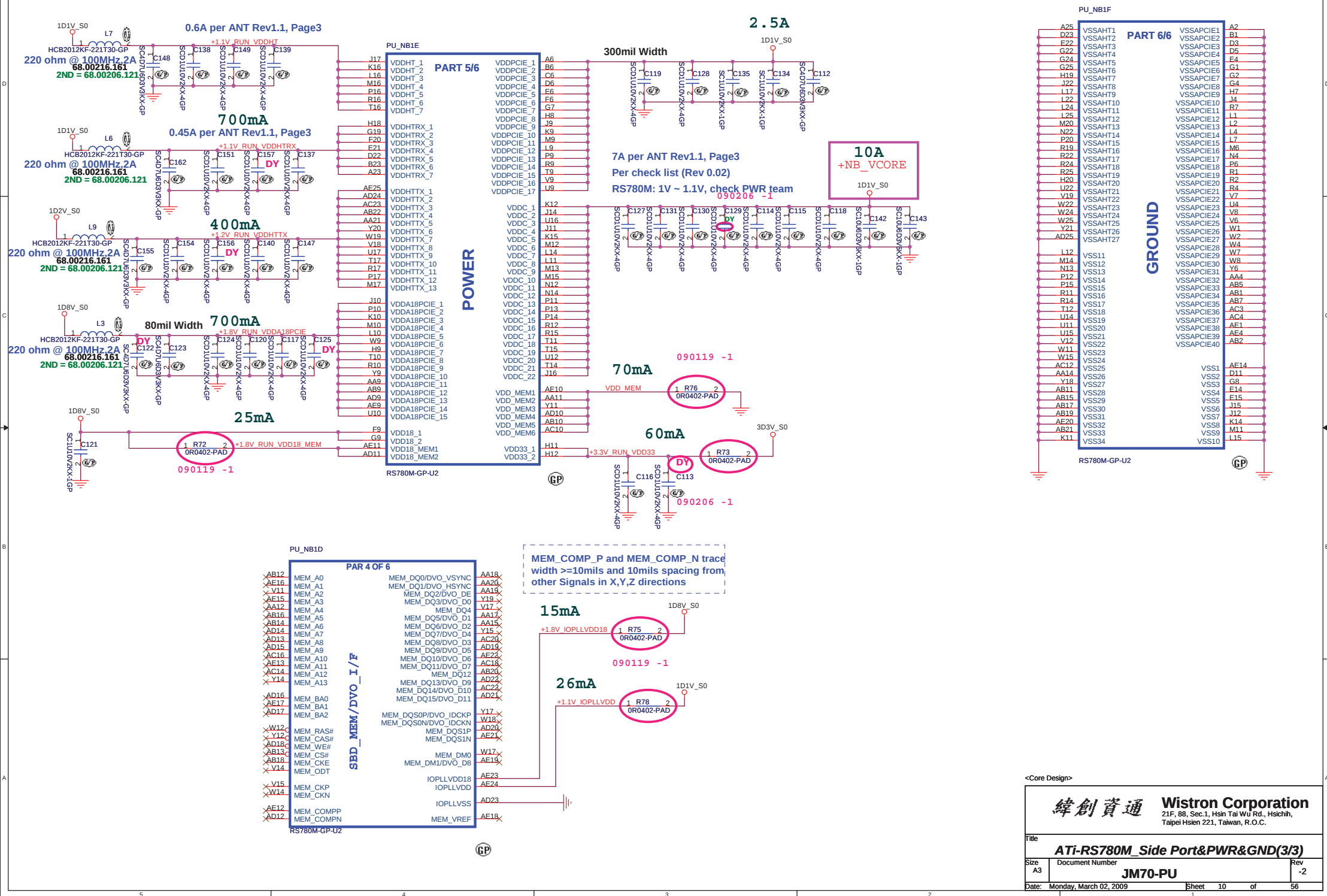


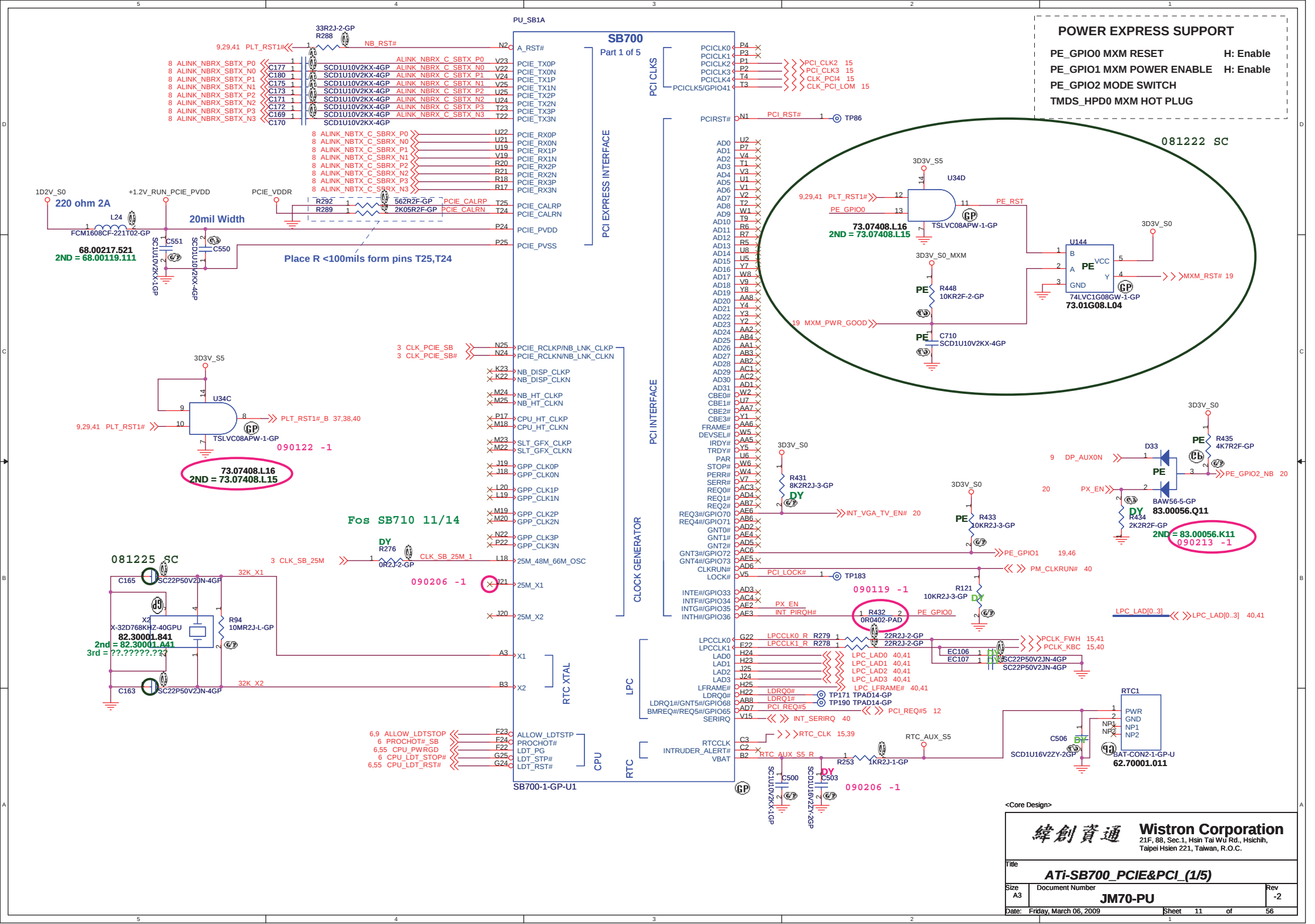


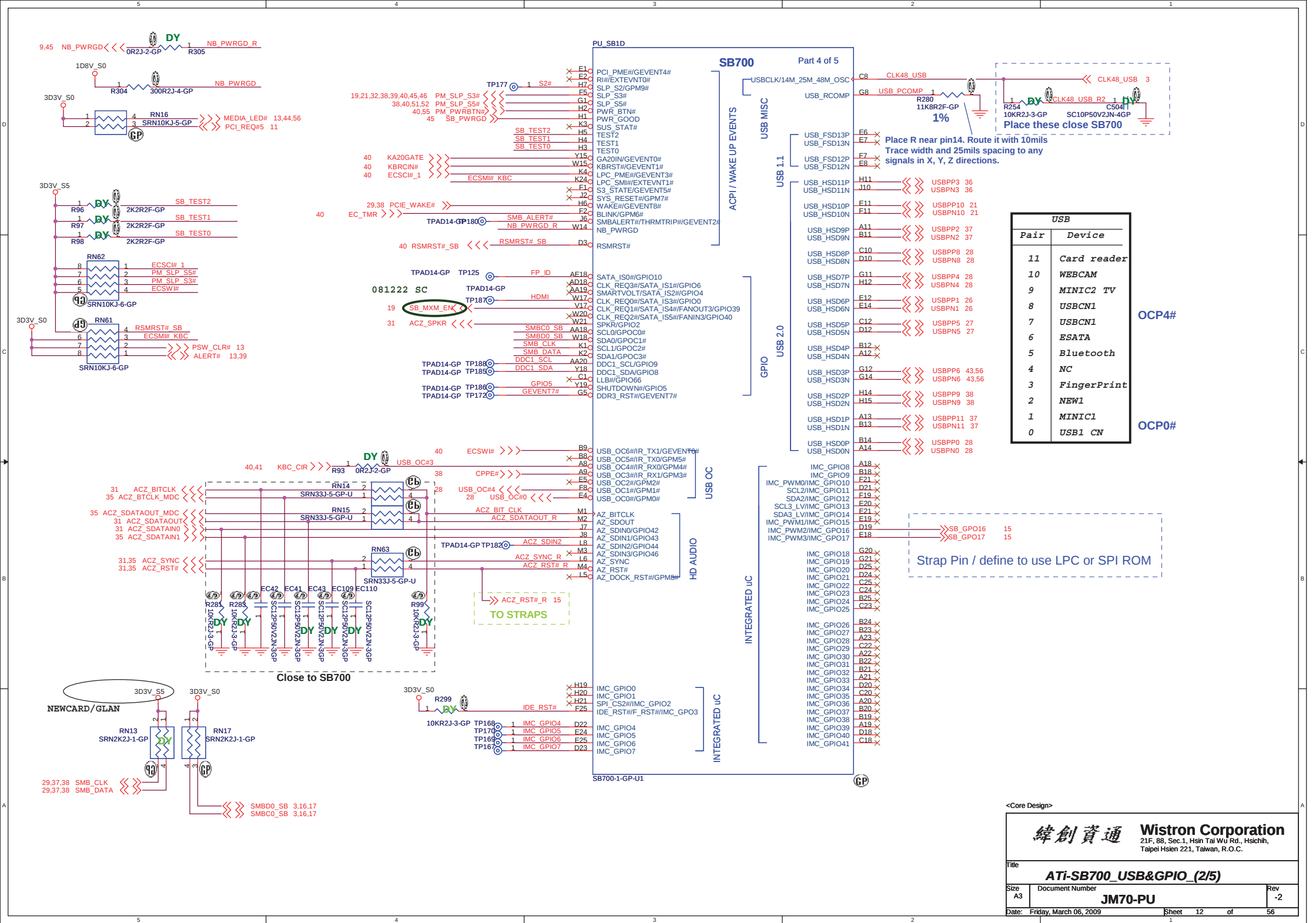
STRAP_DEBUG_BUS_GPIO_ENABLEb
Enables the Test Debug Bus using GPIO.(PIN: RS780M--> VSYNCS#)
* 1 :Disable 0 : Enable

RS780: Enables Side port memory (RS780 use HSYNCS#)
* 1 :Disable 0 : Enable

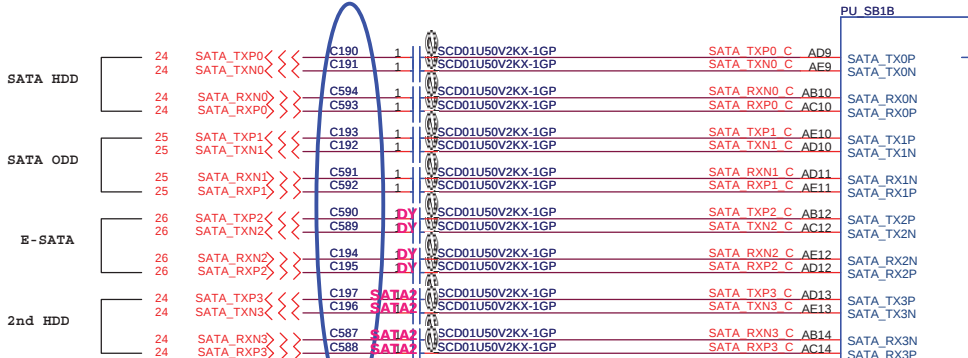
SUS_STAT#
Selects Loading of STRAPS From EEPROM
* 1 : Bypass the loading of EEPROM straps and use Hardware Default Values
0 : I2C Master can load strap values from EEPROM if connected,
or use default values if not connected





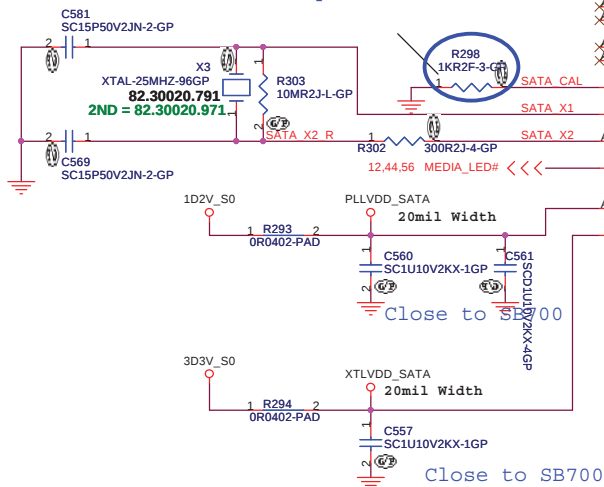


PLACE SATA AC DECOUPLING
CAPS CLOSE TO SB700



090119 -1

Very Close to SB700



Close to SB700

Close to SB700

PU SB18

SB700
Part 2 of 5

SERIAL ATA

SATA PWR

HW MONITOR

SB700-1-GP-U1

ATA 66/100/133

SPI ROM

HW MONITOR



SPI ROM

HW MONITOR



SPI ROM

HW MONITOR



SPI ROM

HW MONITOR



SPI ROM

HW MONITOR



SPI ROM

HW MONITOR



SPI ROM

HW MONITOR



SPI ROM

HW MONITOR

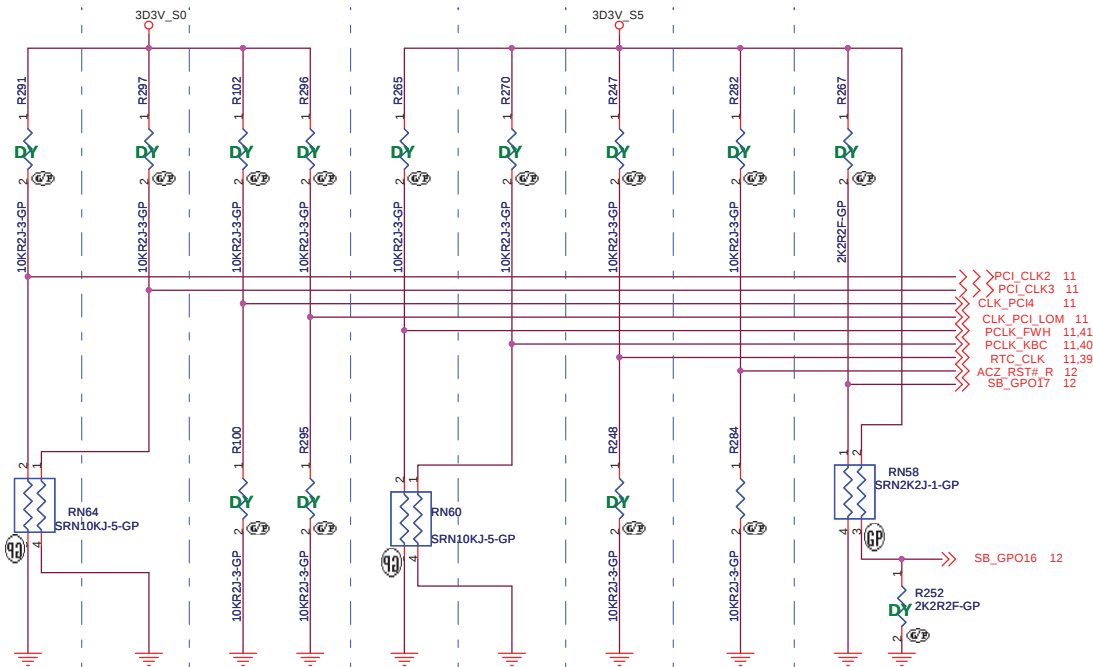


SPI ROM

HW MONITOR



REQUIRED STRAPS
REQUIRED SYSTEM STRAPS



DEBUG STRAPS

	PCI_CLK2	PCI_CLK3	CLK_PCI_LOM CLK_PCI4	PCLK_FWH	PCLK_KBC	RTCCLK	AZ_RST#	SB_GPO17 , SB_GPO16
PULL HIGH	WatchDOG (NB_PWRGD) ENABLED	USE DEBUG STRAPS	RESERVED	IMC ENABLED	CLKGEN ENABLED (Use Internal)	INTERNAL RTC DEFAULT	ENABLE PCI ROM BOOT	ROM TYPE: H, H = Reserved H, L = SPI ROM DEFAULT
PULL LOW	WatchDog (NB_PWRGD) DISABLED DEFAULT	IGNORE DEBUG STRAPS DEFAULT		IMC DISABLED DEFAULT	CLKGEN DISABLED (Use External) DEFAULT	EXT. RTC (PD on X1, apply 32KHz to RTC_CLK)	DISABLE PCI ROM BOOT DEFAULT	L, H = LPC ROM L, L = FWH ROM

NOTE: SB700 HAS INTERNAL 15K PULL UP RESISTOR FOR RTCCLK

	PCI_AD28	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23	PCI_AD30 PCI_AD29
PULL HIGH	USE LONG RESET (DEFAULT)	USE PCI PLL (DEFAULT)	USE ACPI BCLK (DEFAULT)	USE IDE PLL (DEFAULT)	USE DEFAULT PCIE STRAPS (DEFAULT)	Reserved (DEFAULT)	Reserved
PULL LOW	USE SHORT RESET	BYPASS PCI PLL	BYPASS ACPI BCLK	BYPASS IDE PLL	USE EEPROM PCIE STRAPS	Reserved	

Note: SB700 has 15K internal PU FOR PCI_AD[30:23]



5,18 MEM_MB_ADD0 >> 102 A0
5,18 MEM_MB_ADD1 >> 101 A1
5,18 MEM_MB_ADD2 >> 100 A2
5,18 MEM_MB_ADD3 >> 98 A3
5,18 MEM_MB_ADD4 >> 97 A4
5,18 MEM_MB_ADD5 >> 94 A5
5,18 MEM_MB_ADD6 >> 92 A6
5,18 MEM_MB_ADD7 >> 93 A7
5,18 MEM_MB_ADD8 >> 91 A8
5,18 MEM_MB_ADD9 >> 105 A9
5,18 MEM_MB_ADD10 >> 90 A10/AP
5,18 MEM_MB_ADD11 >> 89 A11
5,18 MEM_MB_ADD12 >> 116 A12
5,18 MEM_MB_ADD13 >> 86 A13
5,18 MEM_MB_ADD14 >> 84 A14
5,18 MEM_MB_ADD15 >> 85 A15
5,18 MEM_MB_BANK2 >> A16/BA2
5,18 MEM_MB_BANK0 >> 107 BA0
5,18 MEM_MB_BANK1 >> 106 BA1

5 MEM_MB_DATA0 >> 5 DQ0
5 MEM_MB_DATA1 >> 7 DQ1
5 MEM_MB_DATA2 >> 17 DQ2
5 MEM_MB_DATA3 >> 19 DQ3
5 MEM_MB_DATA4 >> 4 DQ4
5 MEM_MB_DATA5 >> 6 DQ5
5 MEM_MB_DATA6 >> 14 DQ6
5 MEM_MB_DATA7 >> 16 DQ7
5 MEM_MB_DATA8 >> 23 DQ8
5 MEM_MB_DATA9 >> 25 DQ9
5 MEM_MB_DATA10 >> 35 DQ10
5 MEM_MB_DATA11 >> 37 DQ11
5 MEM_MB_DATA12 >> 20 DQ12
5 MEM_MB_DATA13 >> 22 DQ13
5 MEM_MB_DATA14 >> 36 DQ14
5 MEM_MB_DATA15 >> 38 DQ15
5 MEM_MB_DATA16 >> 43 DQ16
5 MEM_MB_DATA17 >> 45 DQ17
5 MEM_MB_DATA18 >> 55 DQ18
5 MEM_MB_DATA19 >> 57 DQ19
5 MEM_MB_DATA20 >> 44 DQ20
5 MEM_MB_DATA21 >> 46 DQ21
5 MEM_MB_DATA22 >> 58 DQ22
5 MEM_MB_DATA23 >> 61 DQ23
5 MEM_MB_DATA24 >> 58 DQ24
5 MEM_MB_DATA25 >> 63 DQ25
5 MEM_MB_DATA26 >> 73 DQ26
5 MEM_MB_DATA27 >> 75 DQ27
5 MEM_MB_DATA28 >> 62 DQ28
5 MEM_MB_DATA29 >> 64 DQ29
5 MEM_MB_DATA30 >> 74 DQ30
5 MEM_MB_DATA31 >> 76 DQ31
5 MEM_MB_DATA32 >> 123 DQ32
5 MEM_MB_DATA33 >> 125 DQ33
5 MEM_MB_DATA34 >> 135 DQ34
5 MEM_MB_DATA35 >> 137 DQ35
5 MEM_MB_DATA36 >> 124 DQ36
5 MEM_MB_DATA37 >> 126 DQ37
5 MEM_MB_DATA38 >> 134 DQ38
5 MEM_MB_DATA39 >> 136 DQ39
5 MEM_MB_DATA40 >> 141 DQ40
5 MEM_MB_DATA41 >> 143 DQ41
5 MEM_MB_DATA42 >> 151 DQ42
5 MEM_MB_DATA43 >> 153 DQ43
5 MEM_MB_DATA44 >> 140 DQ44
5 MEM_MB_DATA45 >> 142 DQ45
5 MEM_MB_DATA46 >> 152 DQ46
5 MEM_MB_DATA47 >> 154 DQ47
5 MEM_MB_DATA48 >> 157 DQ48
5 MEM_MB_DATA49 >> 159 DQ49
5 MEM_MB_DATA50 >> 173 DQ50
5 MEM_MB_DATA51 >> 175 DQ51
5 MEM_MB_DATA52 >> 158 DQ52
5 MEM_MB_DATA53 >> 160 DQ53
5 MEM_MB_DATA54 >> 174 DQ54
5 MEM_MB_DATA55 >> 176 DQ55
5 MEM_MB_DATA56 >> 179 DQ56
5 MEM_MB_DATA57 >> 181 DQ57
5 MEM_MB_DATA58 >> 189 DQ58
5 MEM_MB_DATA59 >> 191 DQ59
5 MEM_MB_DATA60 >> 180 DQ60
5 MEM_MB_DATA61 >> 182 DQ61
5 MEM_MB_DATA62 >> 192 DQ62
5 MEM_MB_DATA63 >> 194 DQ63

5 MEM_MB_DQS0_N >> 11 DQS0#
5 MEM_MB_DQS1_N >> 29 DQS1#
5 MEM_MB_DQS2_N >> 49 DQS2#
5 MEM_MB_DQS3_N >> 68 DQS3#
5 MEM_MB_DQS4_N >> 129 DQS4#
5 MEM_MB_DQS5_N >> 146 DQS5#
5 MEM_MB_DQS6_N >> 167 DQS6#
5 MEM_MB_DQS7_N >> 186 DQS7#
5 MEM_MB_DQS0_P >> 13 DQS0
5 MEM_MB_DQS1_P >> 31 DQS1
5 MEM_MB_DQS2_P >> 51 DQS2
5 MEM_MB_DQS3_P >> 70 DQS3
5 MEM_MB_DQS4_P >> 131 DQS4
5 MEM_MB_DQS5_P >> 148 DQS5
5 MEM_MB_DQS6_P >> 169 DQS6
5 MEM_MB_DQS7_P >> 188 DQS7

5,18 MEM_MB0_ODT0 >> 114 OTD0
5,18 MEM_MB0_ODT1 >> 119 OTD1
VREF_DDR_MEM >> 1 VREF
>> 2 VSS
>> 202 GND
MH1 >> MH1
MH2 >> MH2

5 MEM_MB_DQS0_N >> 11 DQS0#
5 MEM_MB_DQS1_N >> 29 DQS1#
5 MEM_MB_DQS2_N >> 49 DQS2#
5 MEM_MB_DQS3_N >> 68 DQS3#
5 MEM_MB_DQS4_N >> 129 DQS4#
5 MEM_MB_DQS5_N >> 146 DQS5#
5 MEM_MB_DQS6_N >> 167 DQS6#
5 MEM_MB_DQS7_N >> 186 DQS7#
5 MEM_MB_DQS0_P >> 13 DQS0
5 MEM_MB_DQS1_P >> 31 DQS1
5 MEM_MB_DQS2_P >> 51 DQS2
5 MEM_MB_DQS3_P >> 70 DQS3
5 MEM_MB_DQS4_P >> 131 DQS4
5 MEM_MB_DQS5_P >> 148 DQS5
5 MEM_MB_DQS6_P >> 169 DQS6
5 MEM_MB_DQS7_P >> 188 DQS7

5,18 MEM_MB0_ODT0 >> 114 OTD0
5,18 MEM_MB0_ODT1 >> 119 OTD1
VREF_DDR_MEM >> 1 VREF
>> 2 VSS
>> 202 GND
MH1 >> MH1
MH2 >> MH2

Place C2.2uF and 0.1uF < 500mils from DDR connector

PU DM2

NORMAL TYPE

RAS# >> 108 MEM_MB_RAS# 5,18
WE# >> 109 MEM_MB_WE# 5,18
CAS# >> 113 MEM_MB_CAS# 5,18
CS0# >> 110 MEM_MB_CS#0 5,18
CS1# >> 115 MEM_MB_CS#1 5,18
CKE0 >> 79 MEM_MB_CKE0 5,18
CKE1 >> 80 MEM_MB_CKE1 5,18
CK0 >> 30 MEM_MB_CLK0_P 5
CK0# >> 32 MEM_MB_CLK0_N 5
CK1 >> 164 MEM_MB_CLK1_P 5
CK1# >> 166 MEM_MB_CLK1_N 5
DM0 >> 10 MEM_MB_DM0 5
DM1 >> 26 MEM_MB_DM1 5
DM2 >> 52 MEM_MB_DM2 5
DM3 >> 67 MEM_MB_DM3 5
DM4 >> 130 MEM_MB_DM4 5
DM5 >> 147 MEM_MB_DM5 5
DM6 >> 170 MEM_MB_DM6 5
DM7 >> 185 MEM_MB_DM7 5

SDA >> 195 SMBD0_SB 3.12,16
SCL >> 197 SMBC0_SB 3.12,16
VDDSPD >> 199
SA0 >> 198
SA1 >> 200
NC#50 >> 50 X
NC#69 >> 69 X
NC#83 >> 83 X
NC#120 >> 120 X
NC#163/TEST >> 163 X
1D8V_S3 >> 81
VDD >> 82
VDD >> 87
VDD >> 88
VDD >> 95
VDD >> 96
VDD >> 103
VDD >> 104
VDD >> 111
VDD >> 112
VDD >> 117
VDD >> 118
VSS >> 3
VSS >> 8
VSS >> 9
VSS >> 12
VSS >> 15
VSS >> 18
VSS >> 21
VSS >> 24
VSS >> 27
VSS >> 28
VSS >> 33
VSS >> 34
VSS >> 38
VSS >> 40
VSS >> 41
VSS >> 42
VSS >> 47
VSS >> 48
VSS >> 53
VSS >> 54
VSS >> 59
VSS >> 60
VSS >> 65
VSS >> 66
VSS >> 71
VSS >> 72
VSS >> 77
VSS >> 78
VSS >> 121
VSS >> 122
VSS >> 127
VSS >> 128
VSS >> 132
VSS >> 133
VSS >> 138
VSS >> 139
VSS >> 144
VSS >> 145
VSS >> 149
VSS >> 150
VSS >> 155
VSS >> 156
VSS >> 161
VSS >> 162
VSS >> 165
VSS >> 168
VSS >> 171
VSS >> 172
VSS >> 173
VSS >> 178
VSS >> 183
VSS >> 184
VSS >> 187
VSS >> 190
VSS >> 193
VSS >> 196
GND >> 201
MH2 >> MH2

10KR2J-3-GP
(A2)

PLACE CLOSE TO PROCESSOR
WITHIN 1.5 INCH
MEM_MB_CLK0_P
C247 SC1D5P50V2CN-1GP
MEM_MB_CLK0_N
MEM_MB_CLK1_P
C243 SC1D5P50V2CN-1GP
MEM_MB_CLK1_N

081225 SC

62.10017.E21

ZND = 62.10017.071

HI 9.2mm

<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title
DDR_SO-DIMM SKT_2

Size
Custom

Document Number
JM70-PU

Date
Friday, March 06, 2009

Sheet
17

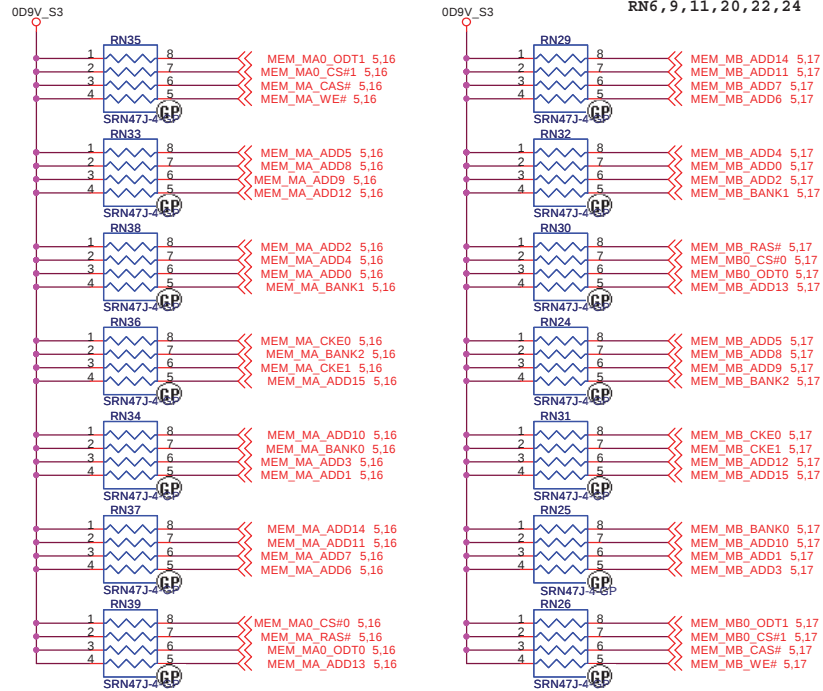
of
56

Rev
-2

PARALLEL TERMINATION

Put decap near power(0.9V) and pull-up resistor

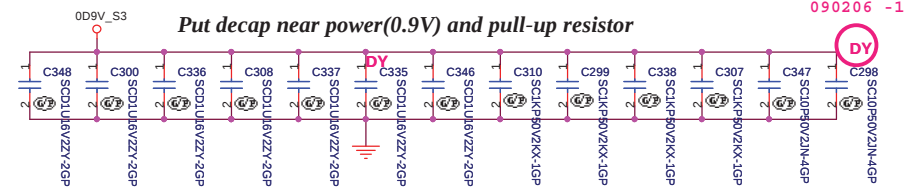
Net swap 11/14
RN6,9,11,20,22,24



Do not share the Term resistor between the DDR address and Control Signals.

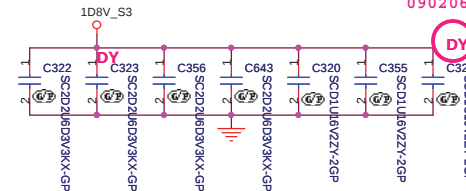
Decoupling Capacitor

Put decap near power(0.9V) and pull-up resistor



Place these Caps near DM1

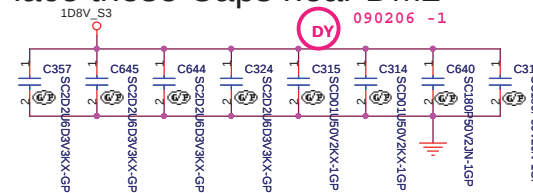
090206 -1



Layout Note:
Place one cap close to every 2 pullup
resistors terminated to 0D9V_S3

Place these Caps near DM2

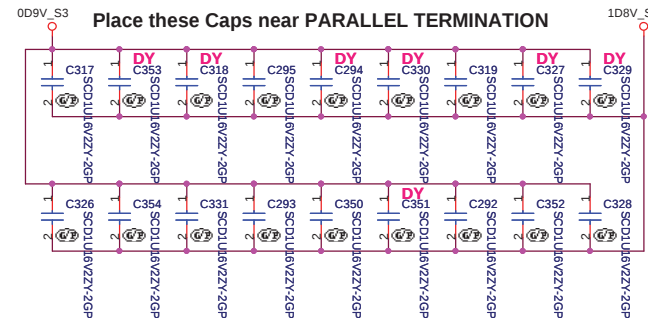
090206 -1



Layout Note:
Place one cap close to every 2 pullup
resistors terminated to 0D9V_S3

Place these Caps near PARALLEL TERMINATION

090209 -1



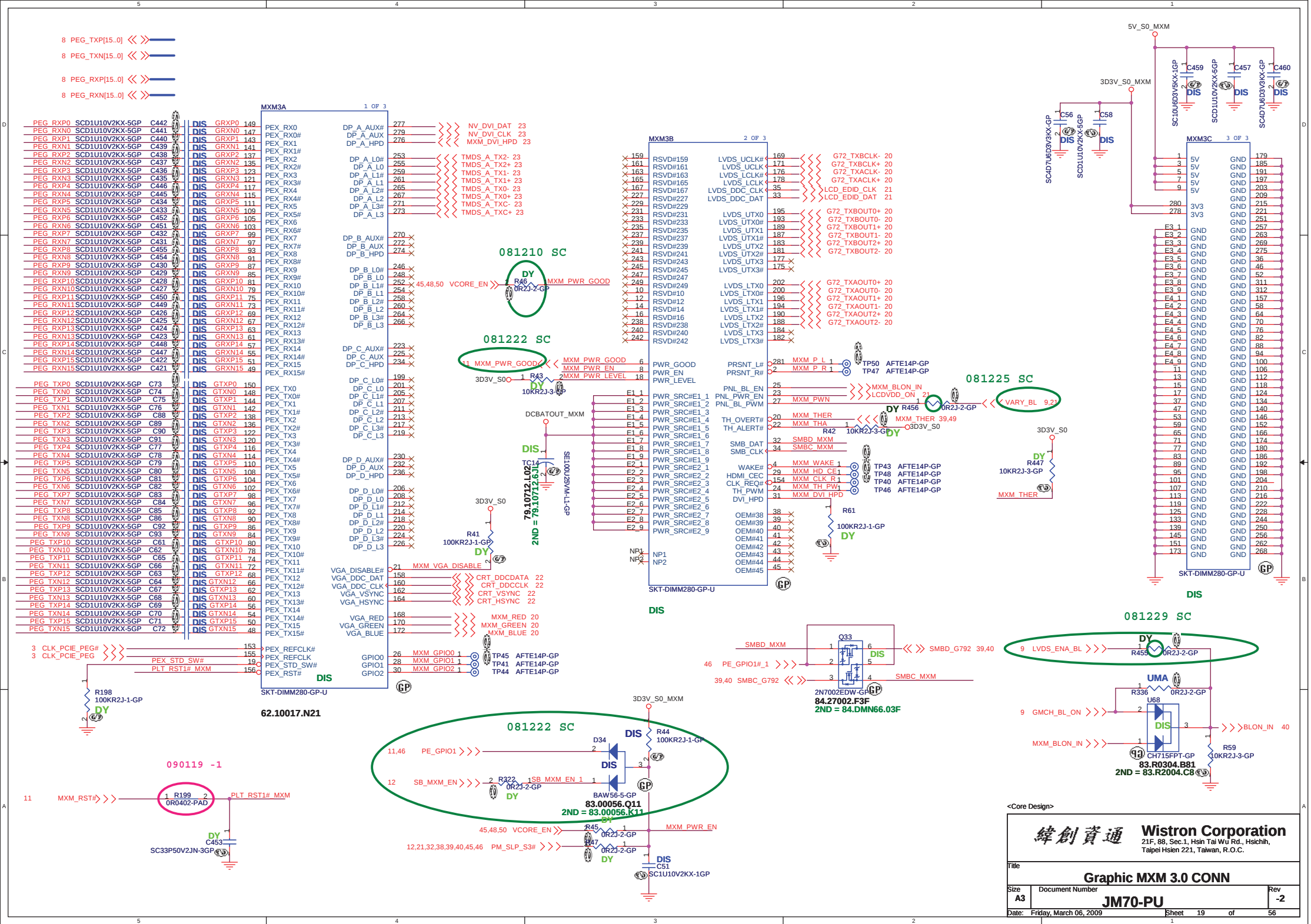
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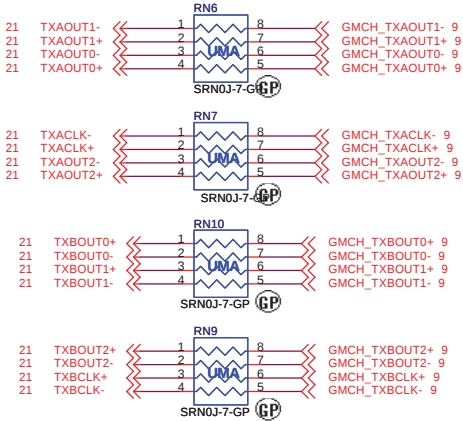
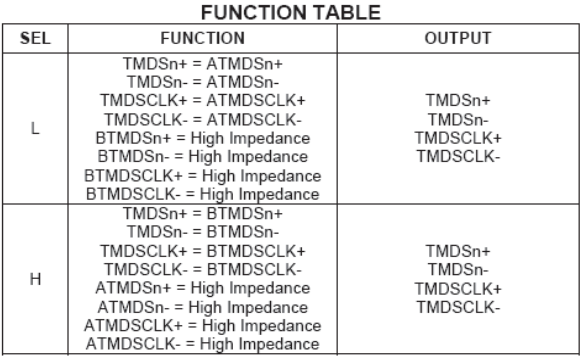
緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title	DDR DAMPING & TERMINATION
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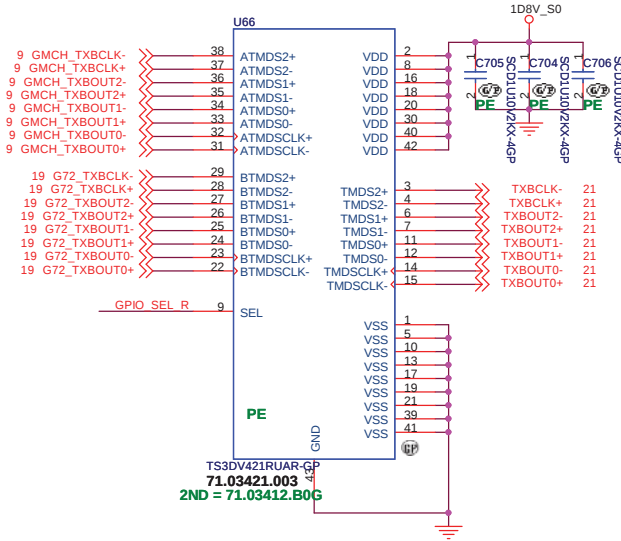
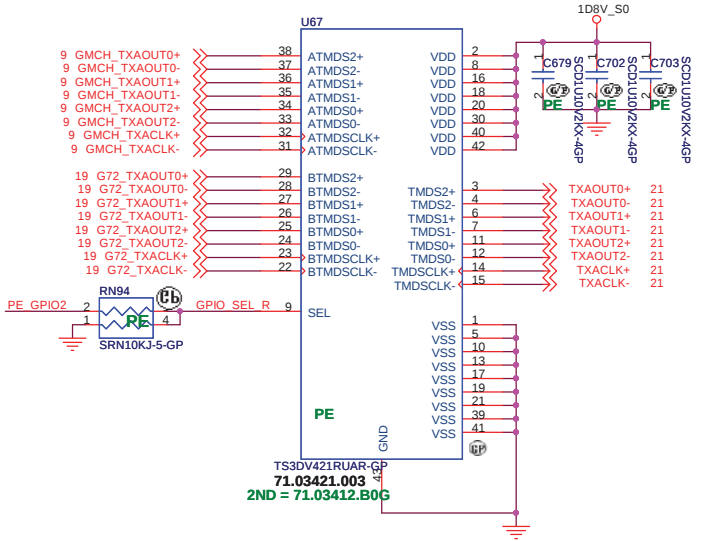
Size A3	Document Number JM70-PU	Rev -2
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Date: Friday, March 06, 2009 Sheet 18 of 56



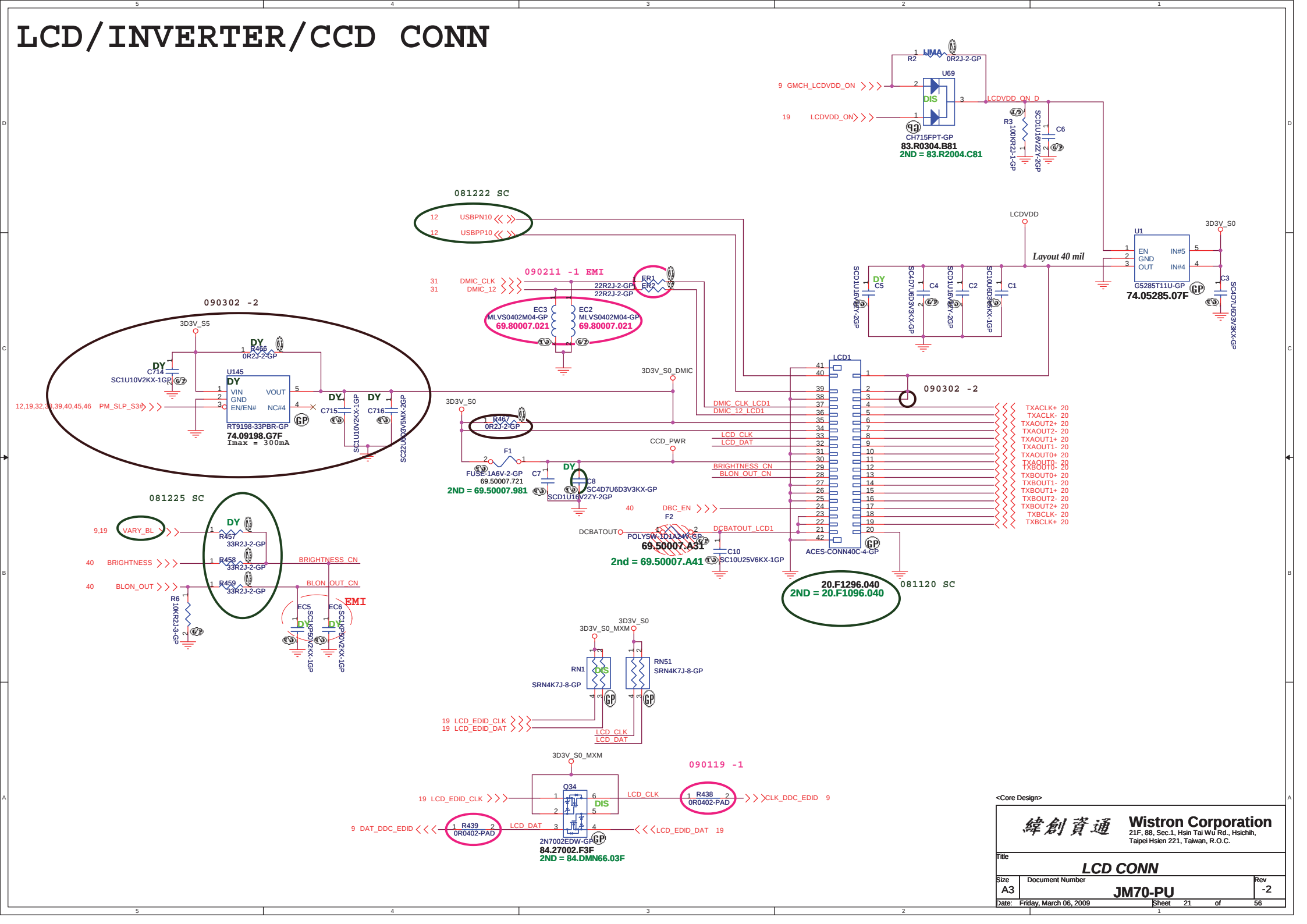
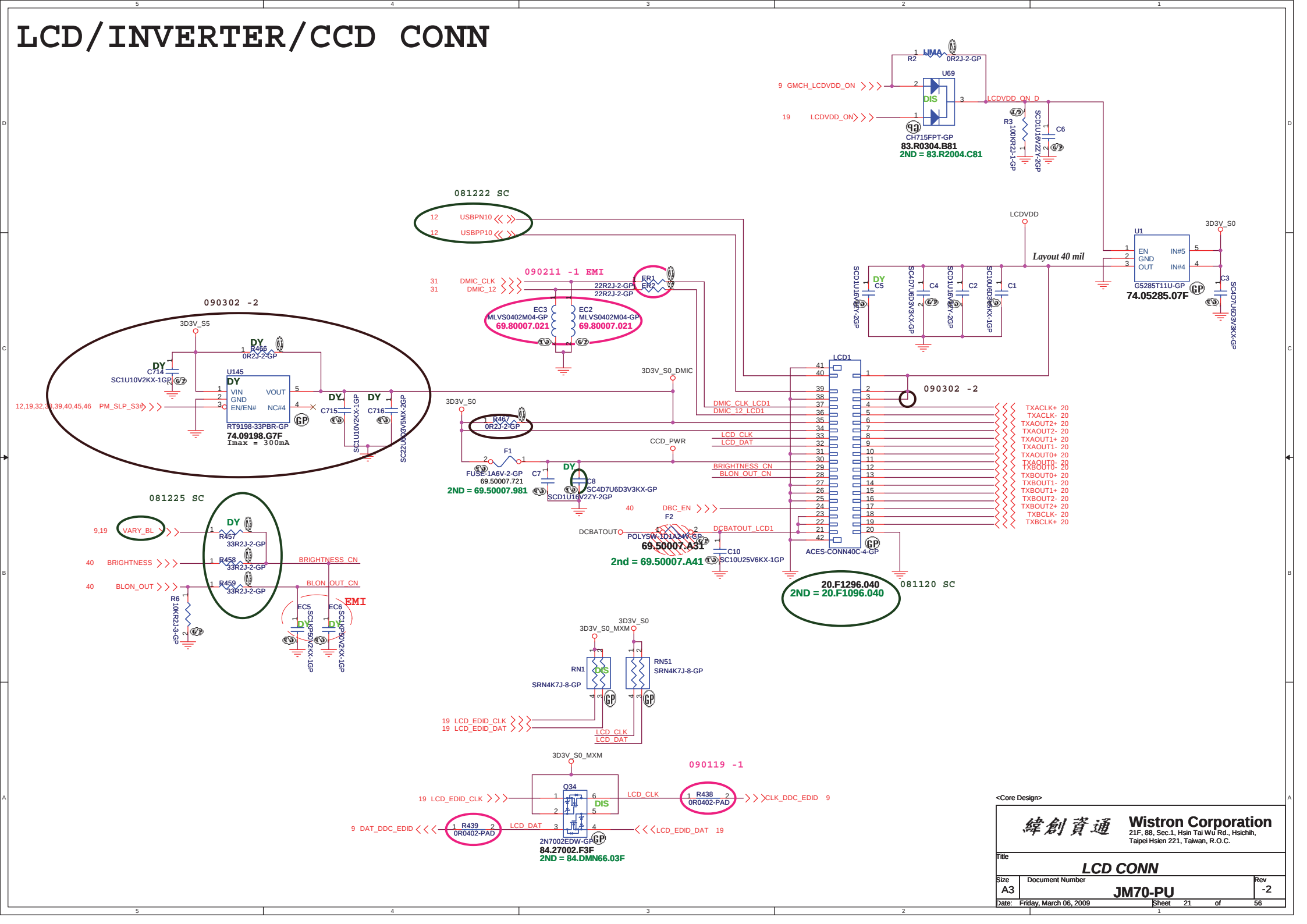
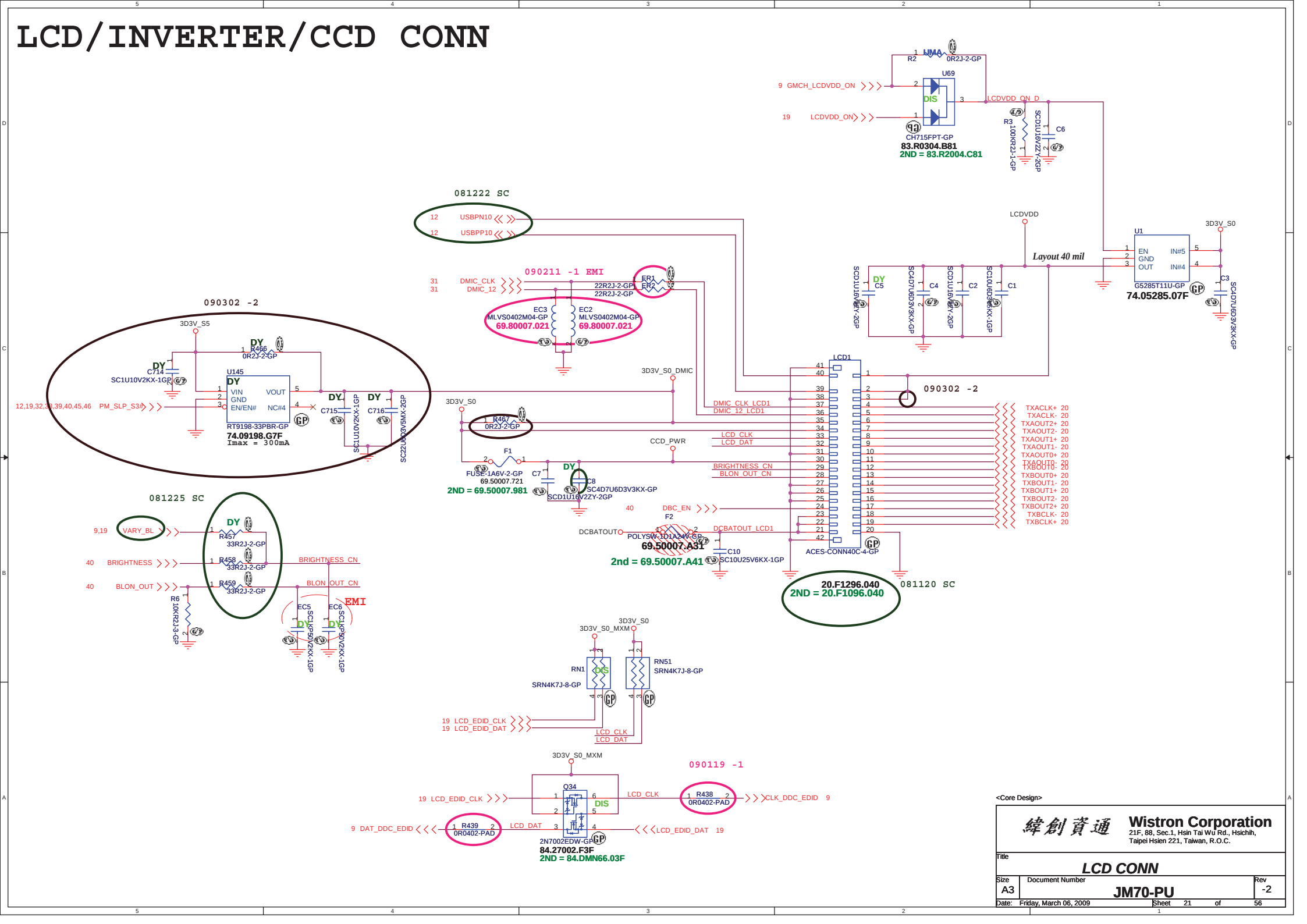
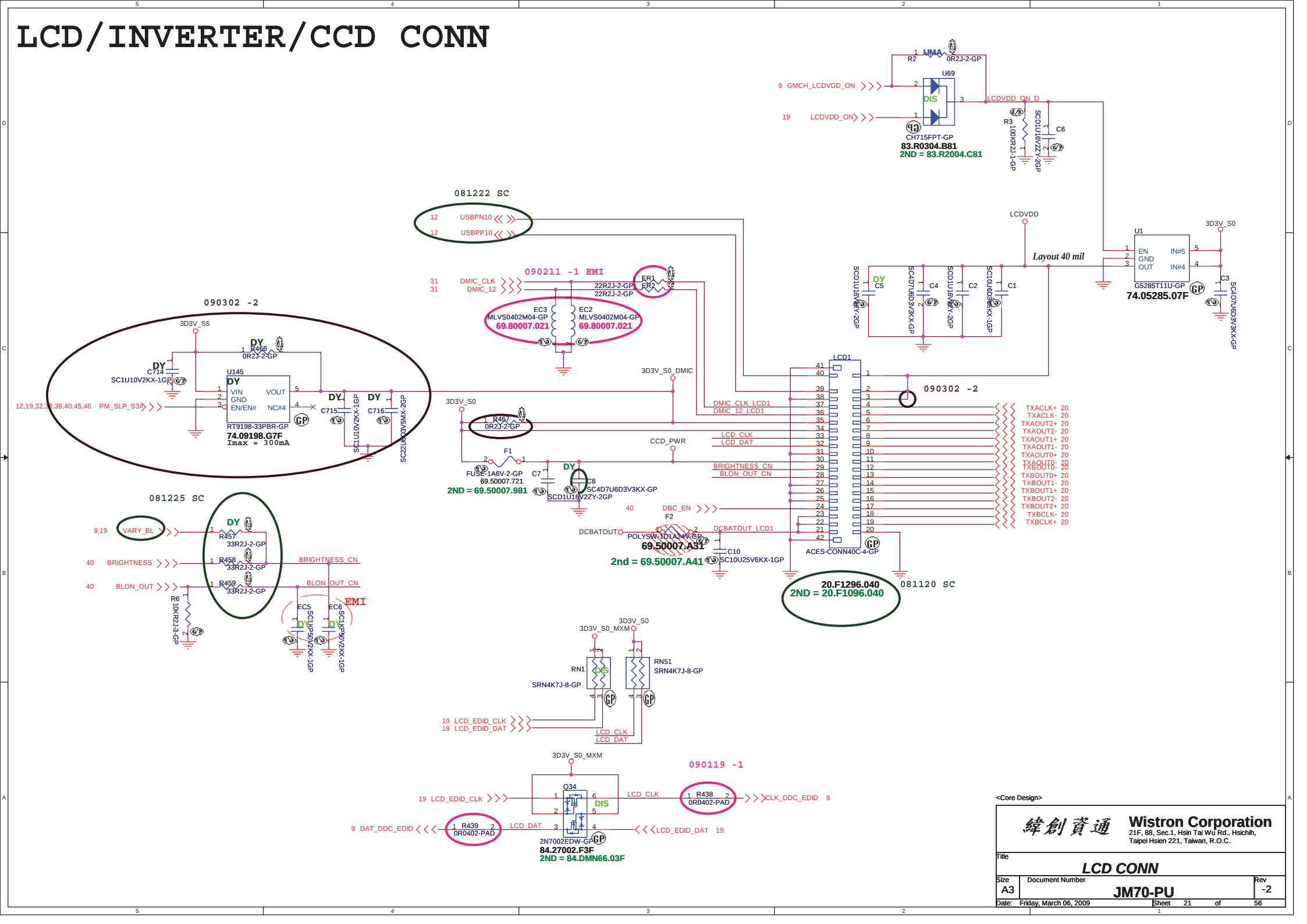


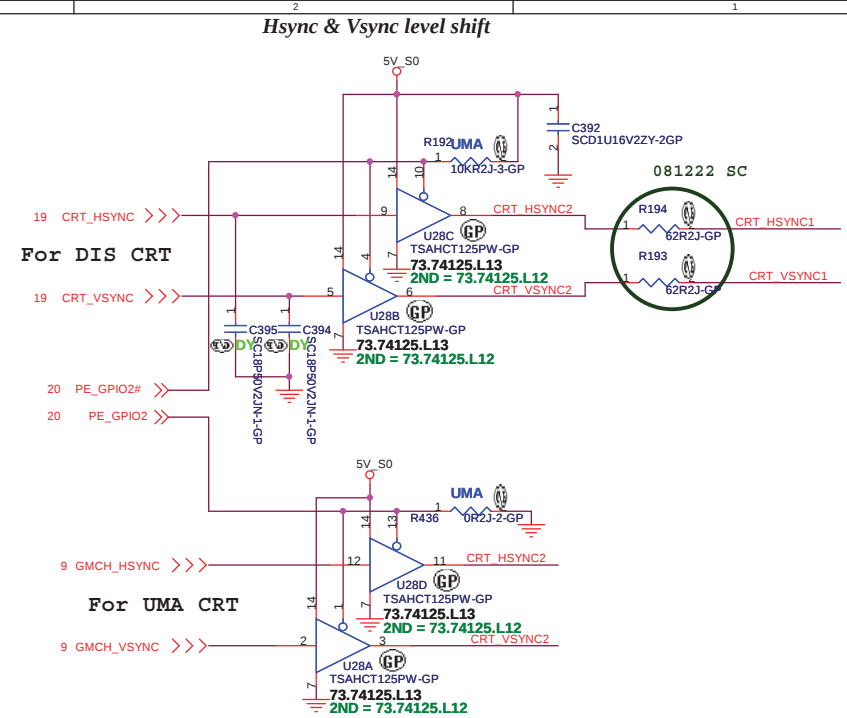
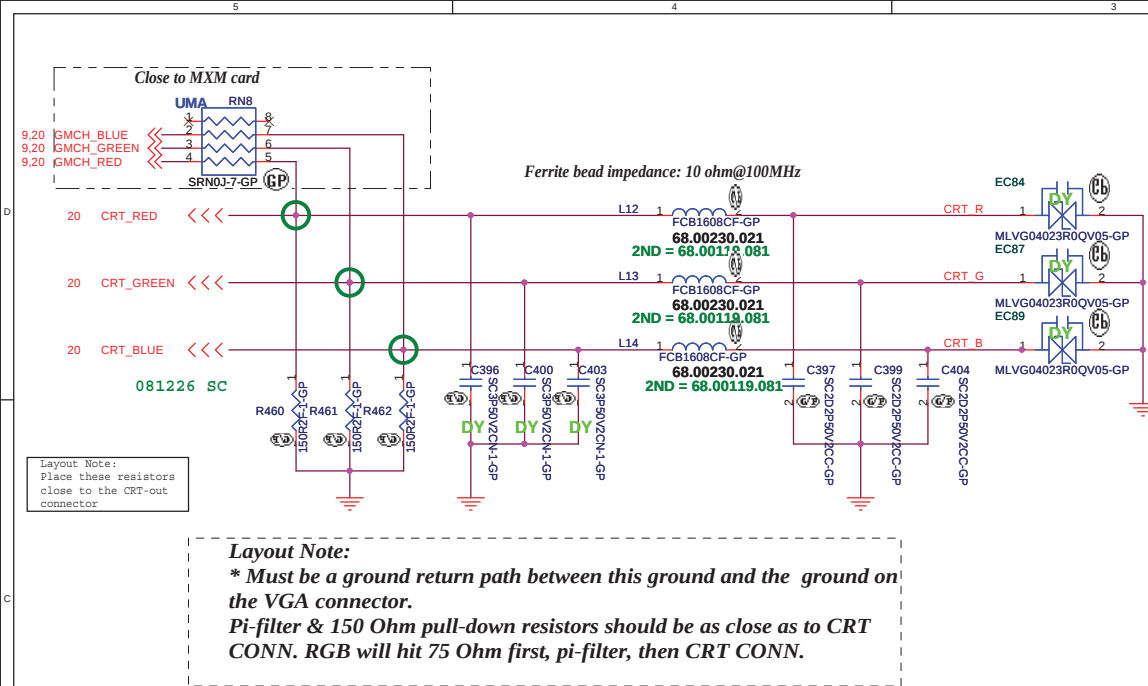
$\bar{E}$	S	YA	YB	YC	YD	Function
H	X	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Disable
L	L	IA0	IB0	IC0	ID0	S = 0
L	H	IA1	IB1	IC1	ID1	S = 1



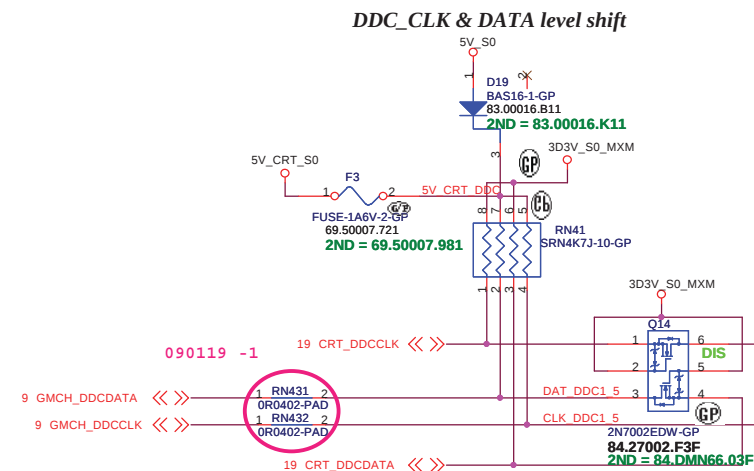
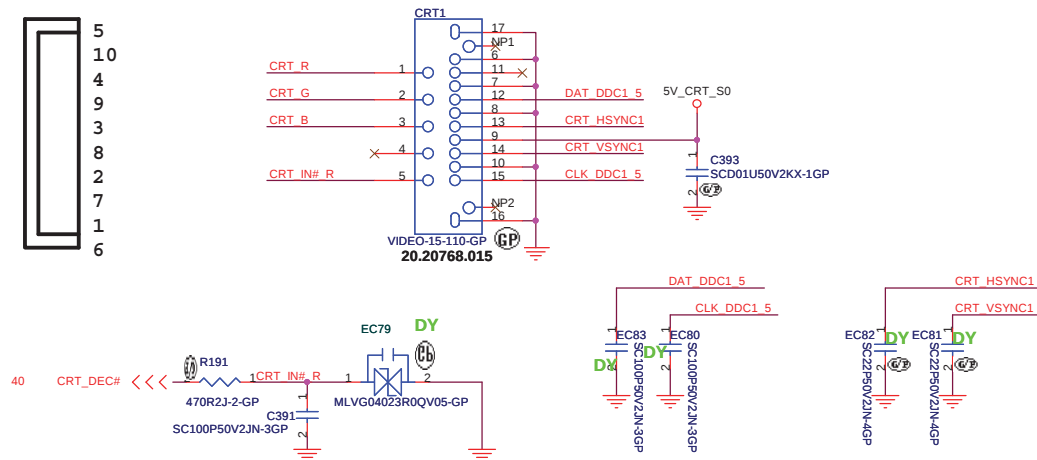
DISPLAY SUPPORT TABLE

	PX_EN	PE_GPIO2_NB	INT_VGA_EN#	DISPLAY OUTPUT
IGP only mode	0	X	0	IGP{ LVDS,VGA,HDMI,DP}
MXM only mode	0	X	1	MXM{ LVDS,VGA,HDMI,DP}
Power Express mode	1	0/1	X	*MXM(VGA,HDMI,DP); MXM/IGP(LVDS)
IGP + MXM	0	X	0	IGP{ LVDS,VGA,HDMI}

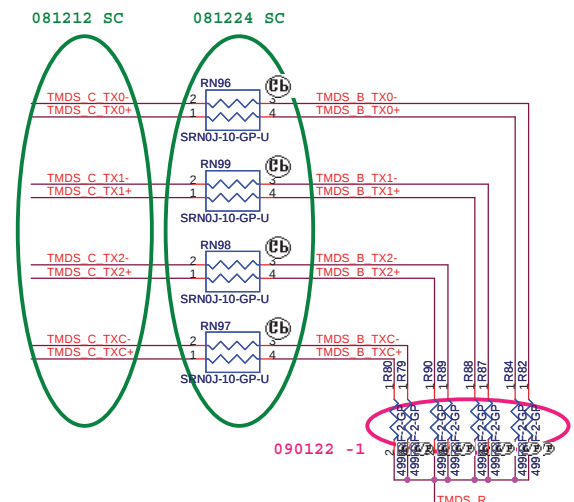
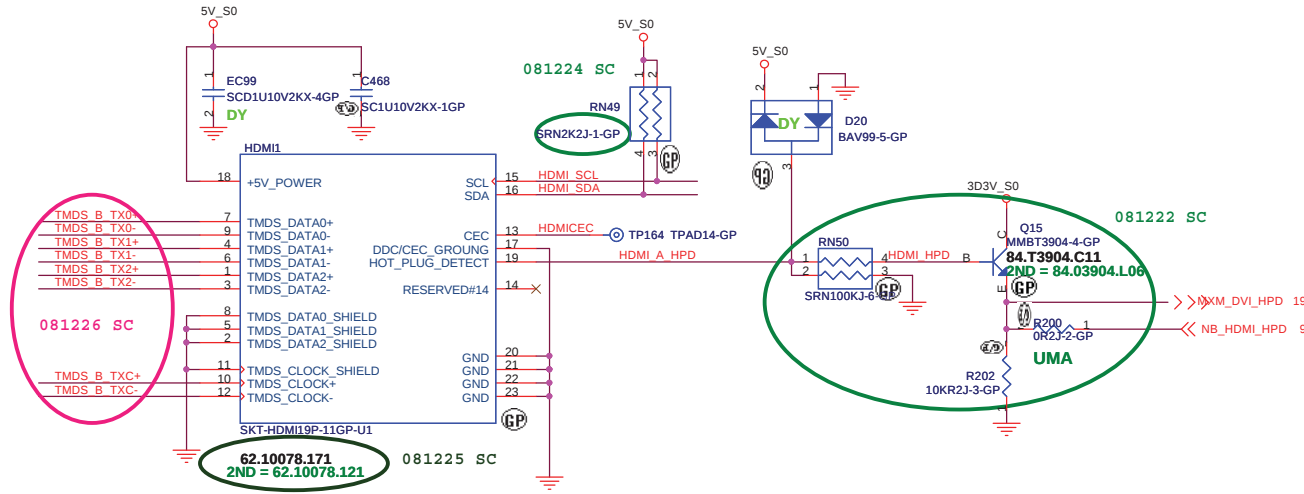
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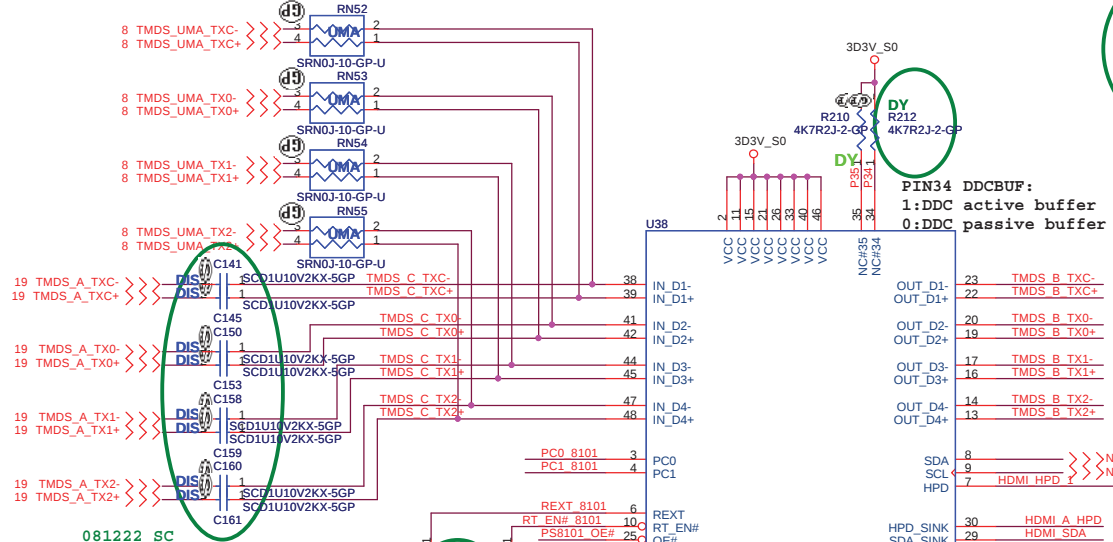
CRT I/F & CONNECTOR



<Core Design>

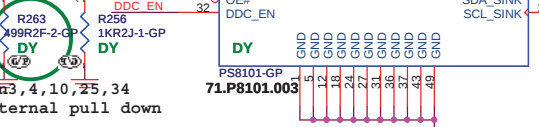
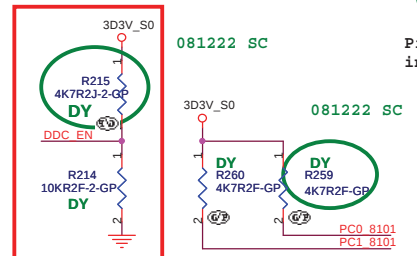
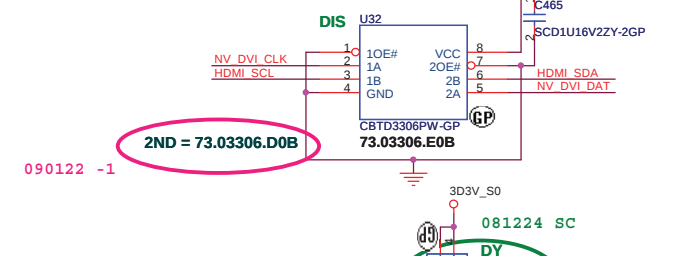


Place Near MXM3 Connector

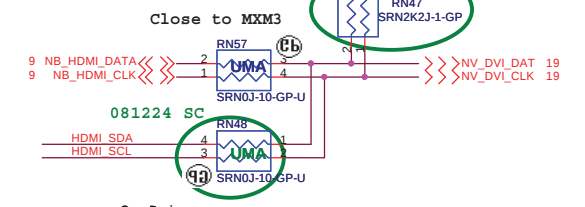
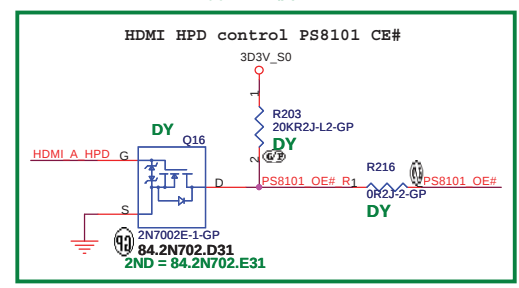
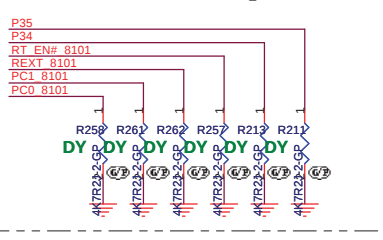


HDMI SM BUS LEVEL shifter

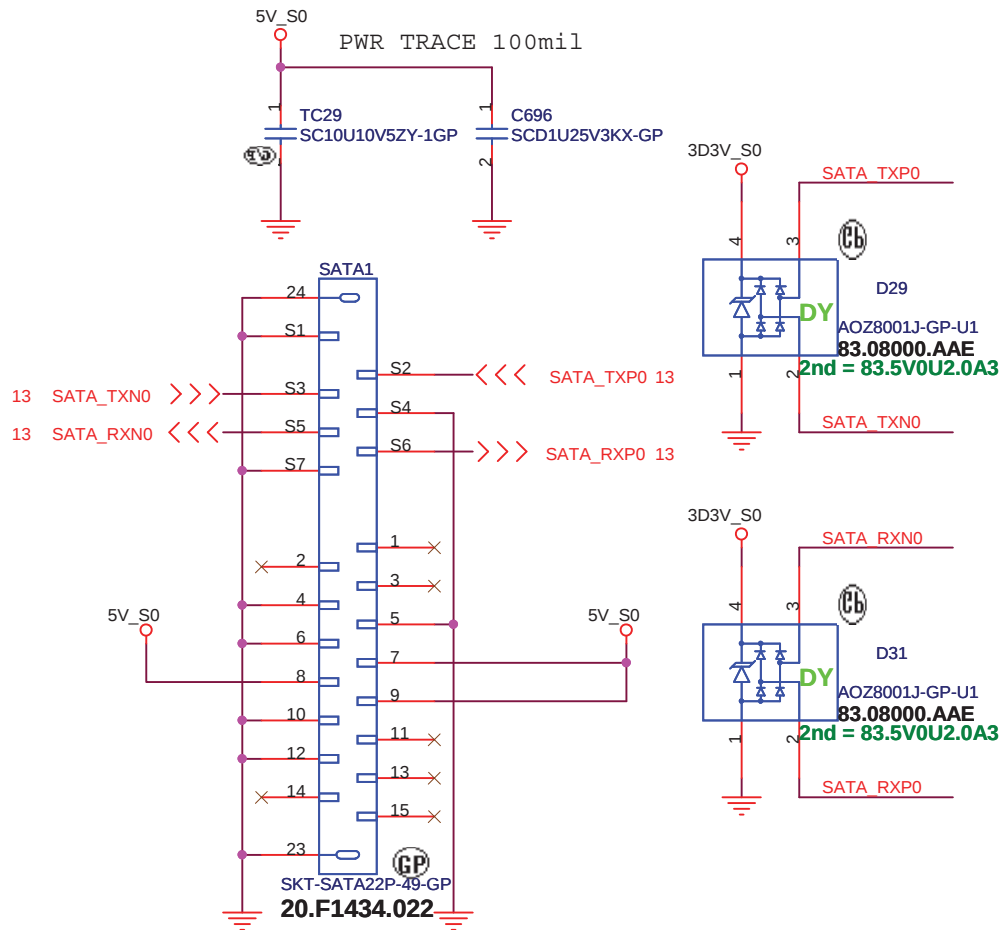
Close HDMI1



PI3VDP411 co-layout

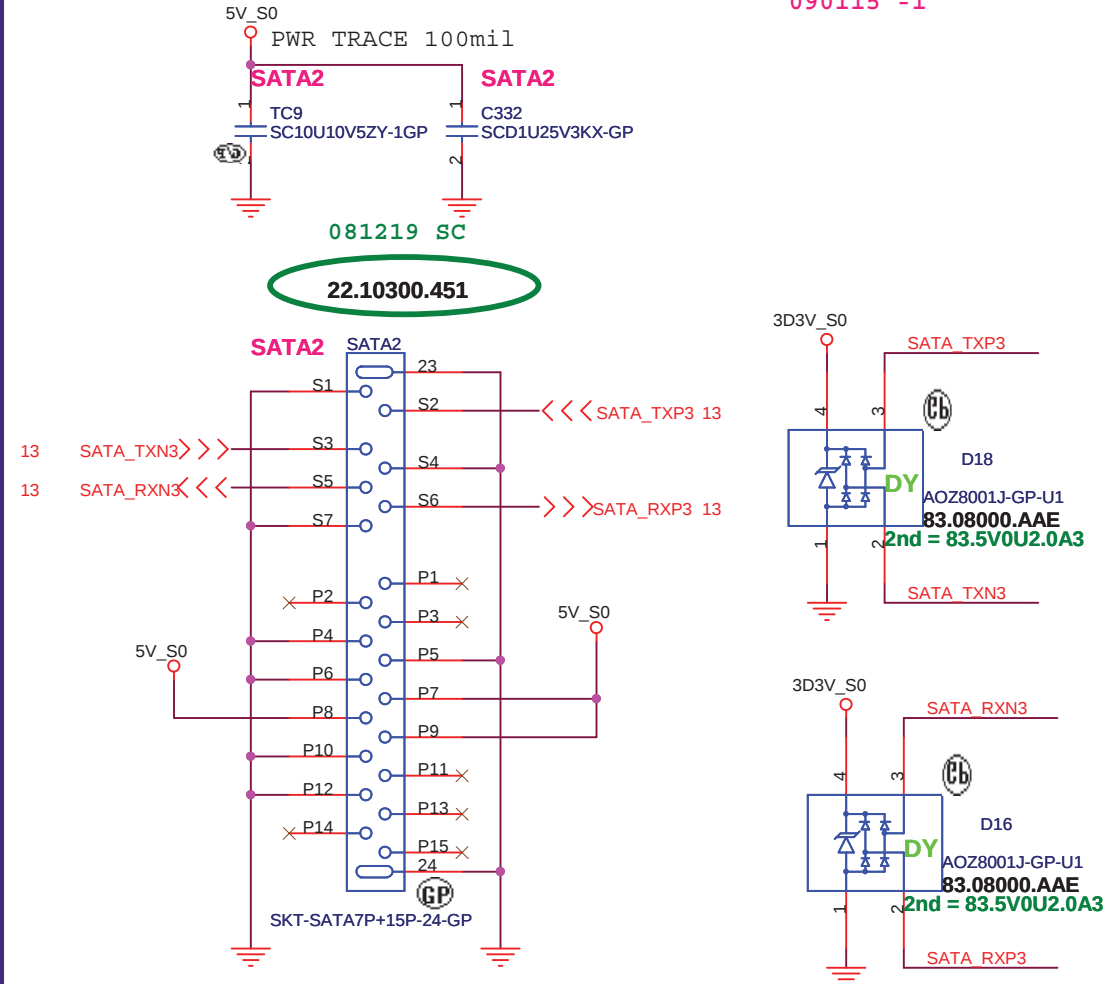


SATA HDD Connector



2ND SATA HDD Connector

090115 -1



<Core Design>

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Title

HDD

Size

A4

Document Number

JM70-PU

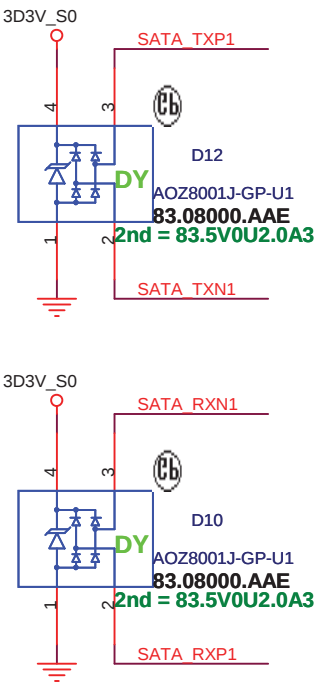
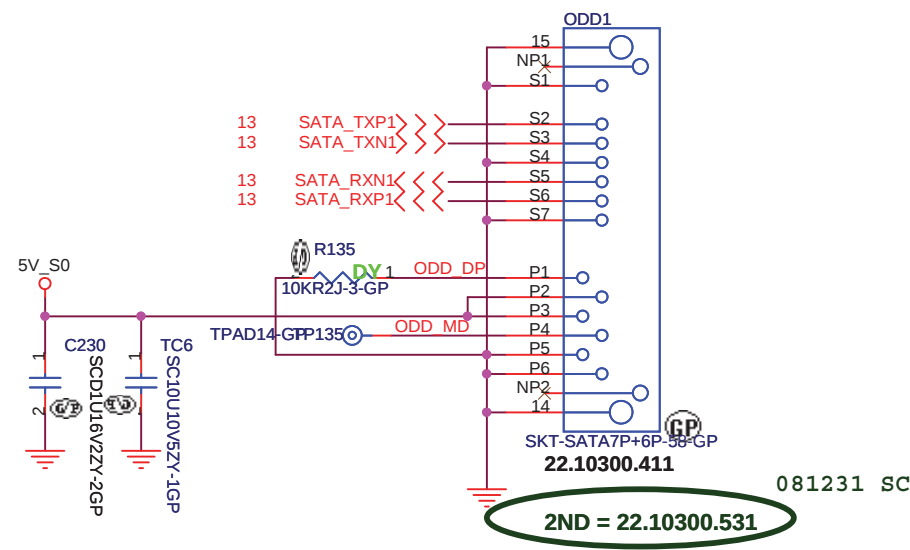
Rev

-2

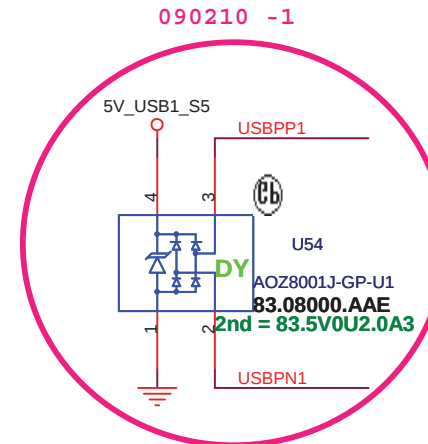
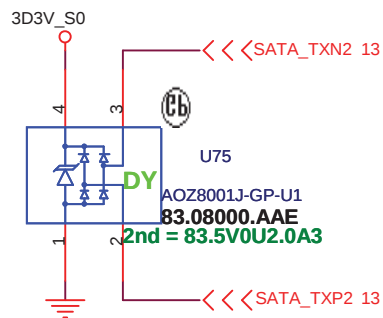
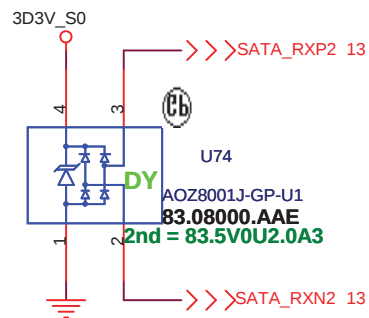
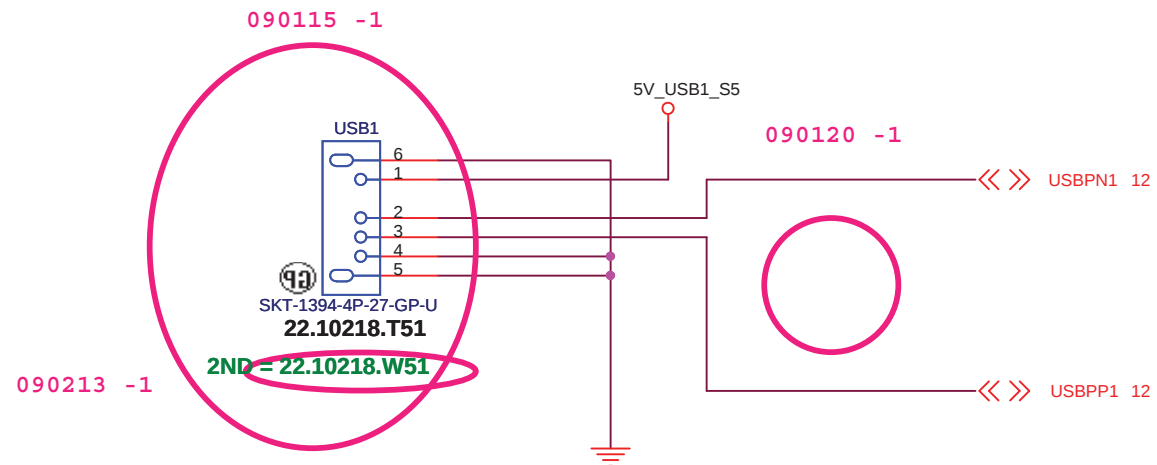
Date: Friday, March 06, 2009

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ODD Connector



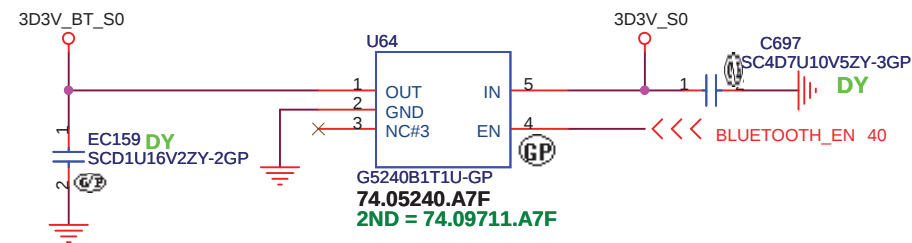
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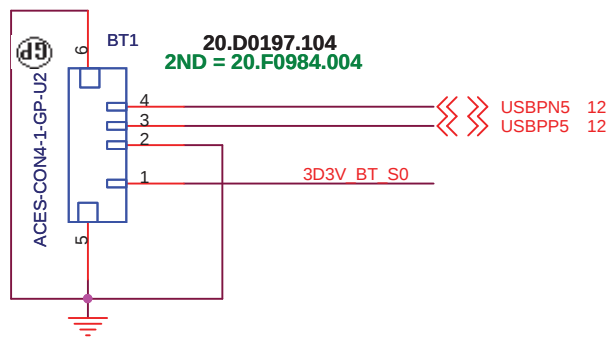
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緯創資通		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
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BLUETOOTH MODULE



EC40 put near BLUE1 / all USB put one
choke near connector by EMI request



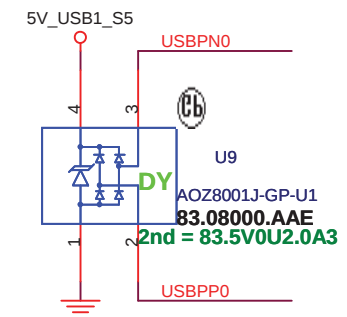
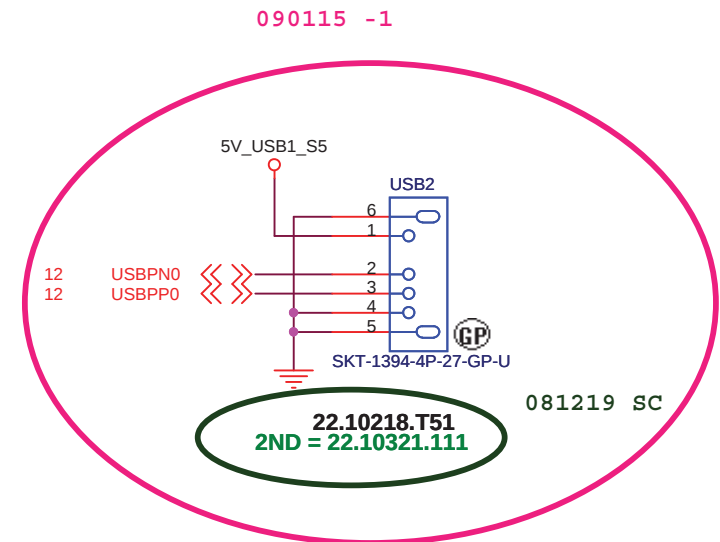
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BLUETOOTH

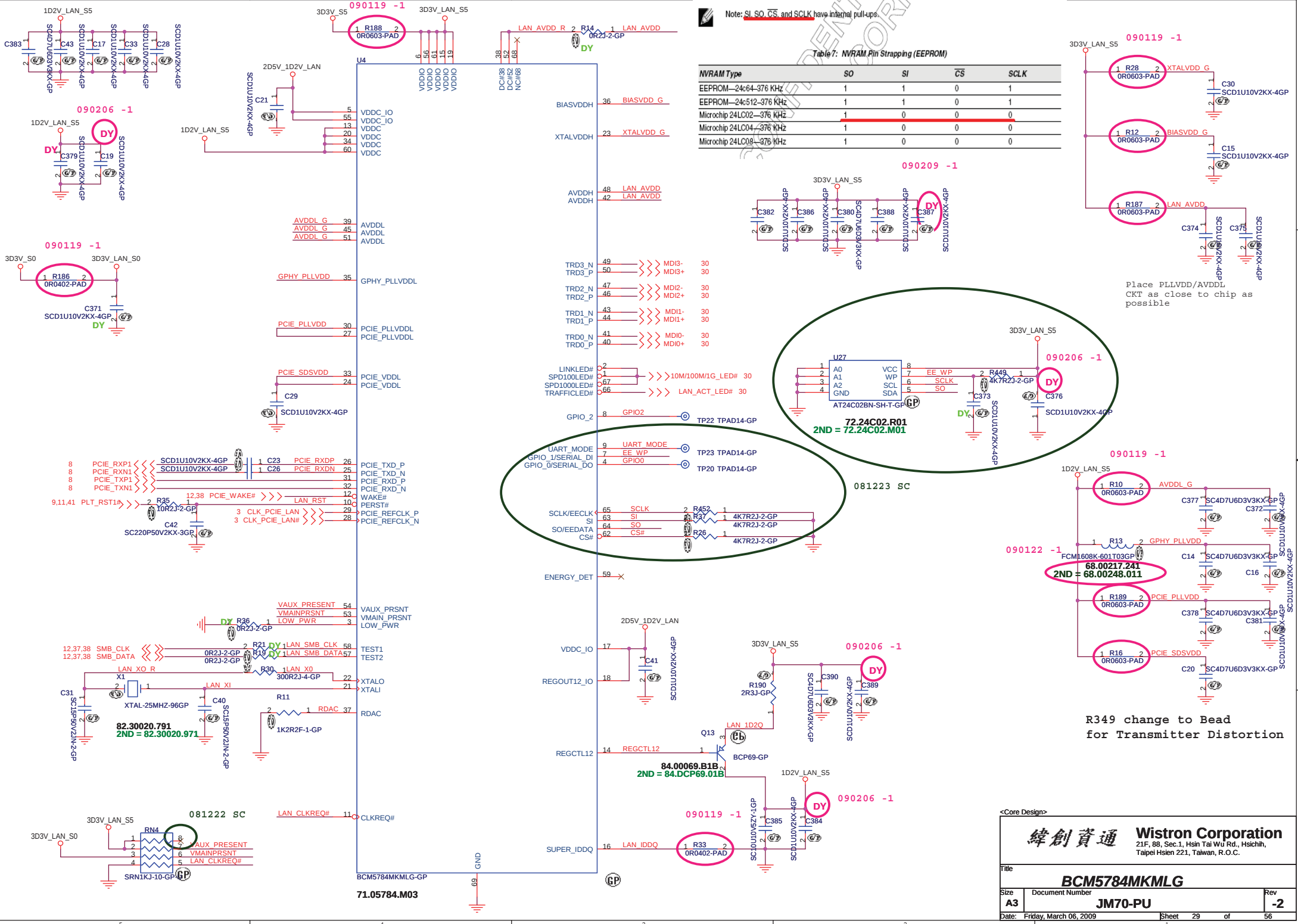
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Taipei Hsien 221, Taiwan, R.O.C.

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Note: SI, SO, CS, and SCLK have internal pull-ups.

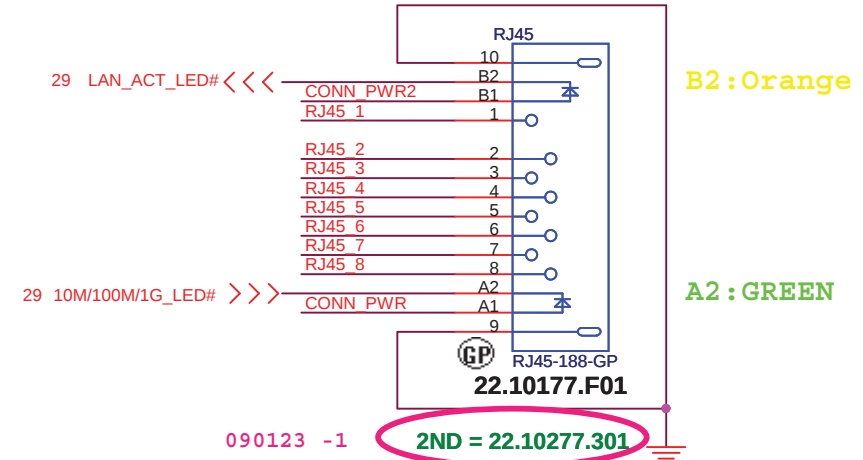
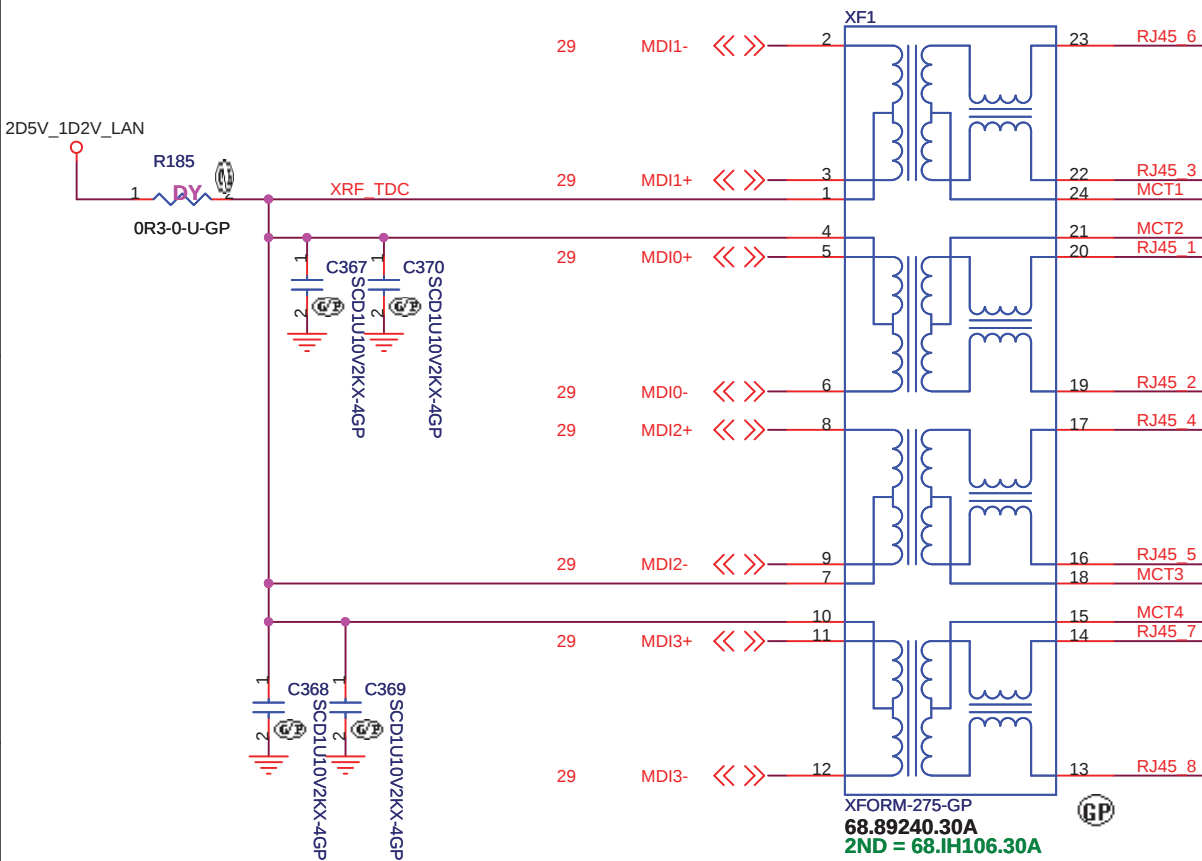
Table 7: NVRAM Pin Strapping (EEPROM)

NVRAM Type	SO	SI	CS	SCLK
EEPROM—24c64—376 KHz	1	1	0	1
EEPROM—24c512—376 KHz	1	1	0	1
Microchip 24LC02—376 KHz	1	0	0	0
Microchip 24LC04—376 KHz	1	0	0	0
Microchip 24LC08—376 KHz	1	0	0	0

Place PLLVDD/AVDDL CKT as close to chip as possible

R349 change to Bead for Transmitter Distortion

LAN Connector

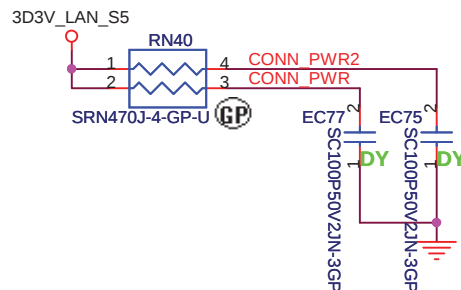
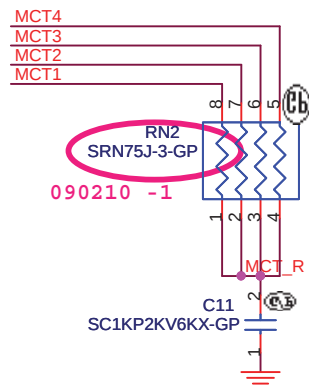
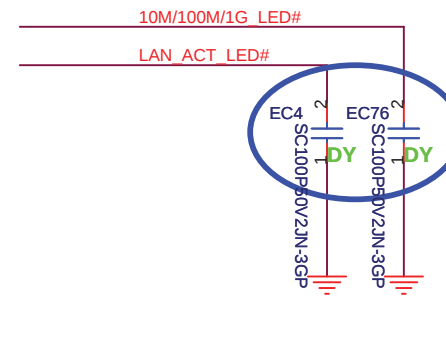


Green(A2), behavior is the same for 10/100/1000 bits

LAN Data: Yellow(B2), when LAN is transferring data.

- 1.route on bottom as differential pairs.
- 2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.
- 3.No vias, No 90 degree bends.
- 4.pairs must be equal lengths.
- 5.6mil trace width,12mil separation.
- 6.36mil between pairs and any other trace.
- 7.Must not cross ground moat,except RJ-45 moat.

For EMI Near LAN1 CONN



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Title

LAN CONN

Size

A4

Document Number

JM70-PU

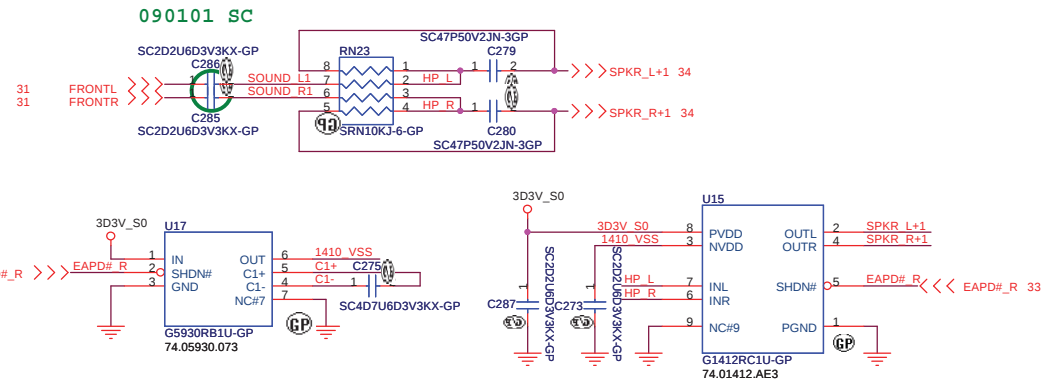
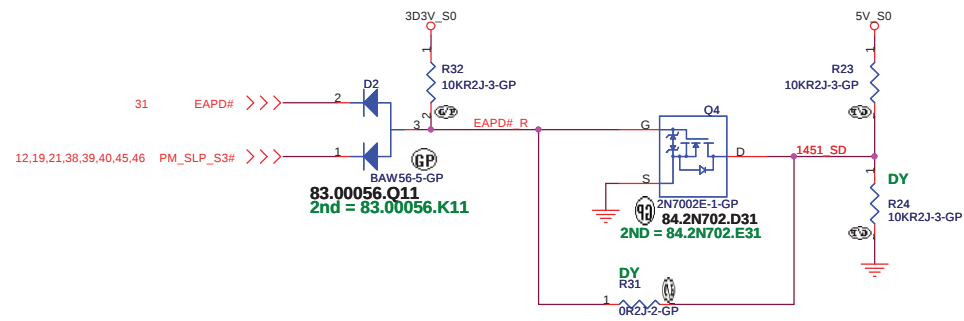
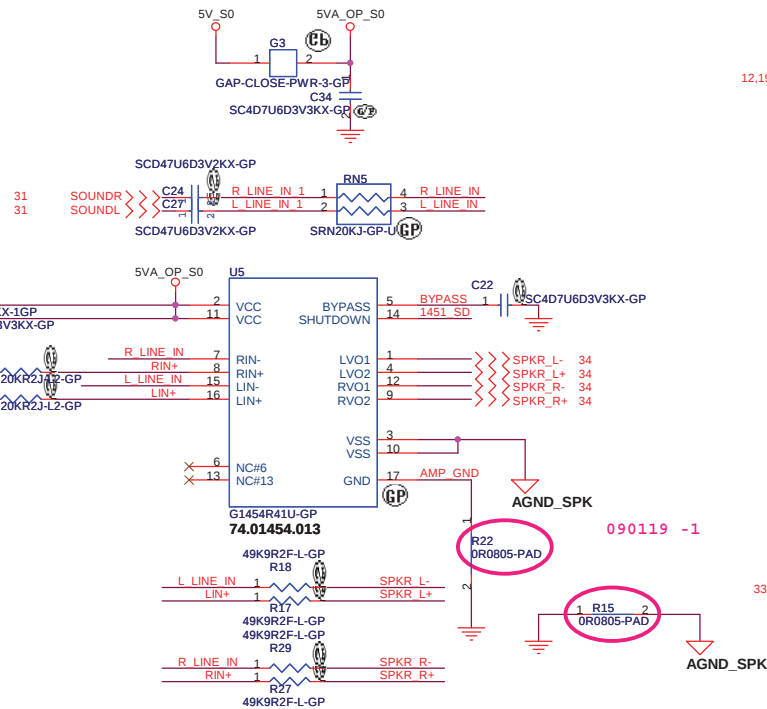
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AUDIO OP AMPLIFIER

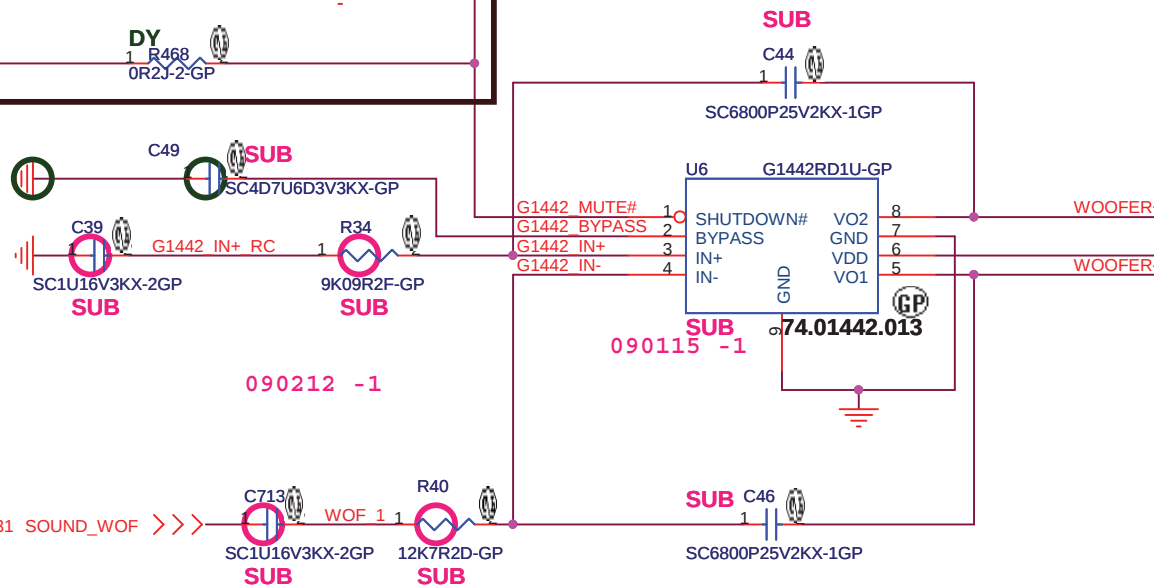
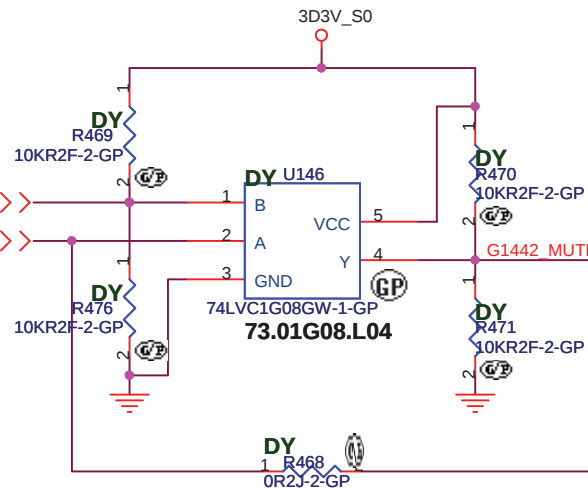


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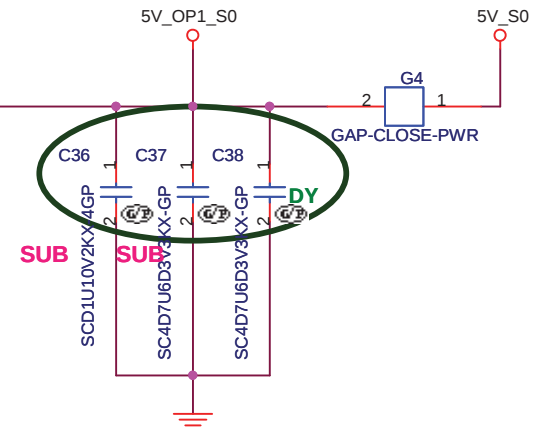
緯創資通 Wistron Corporation
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 Taipei Hsien 221, Taiwan, R.O.C.

Title		
AUDIO AMP		
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090305 -2

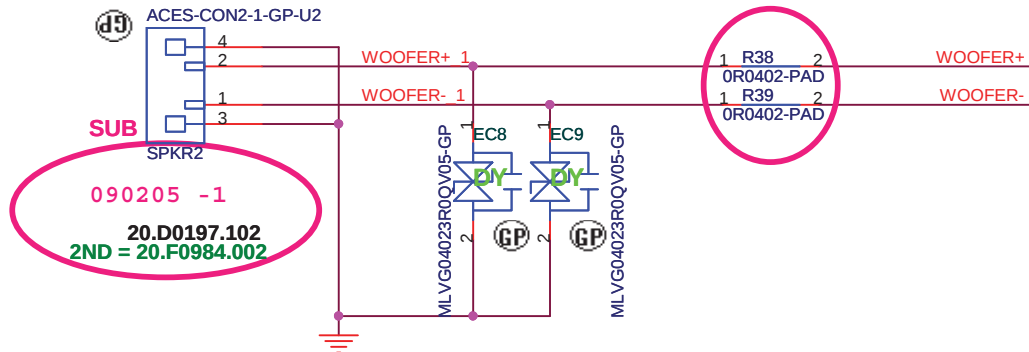


081220 SC



SUBWOOFER CONN.

090119 -1



<Core Design>

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Title

Audio AMP for Subwoofer

Size

Document Number

JM70-PU

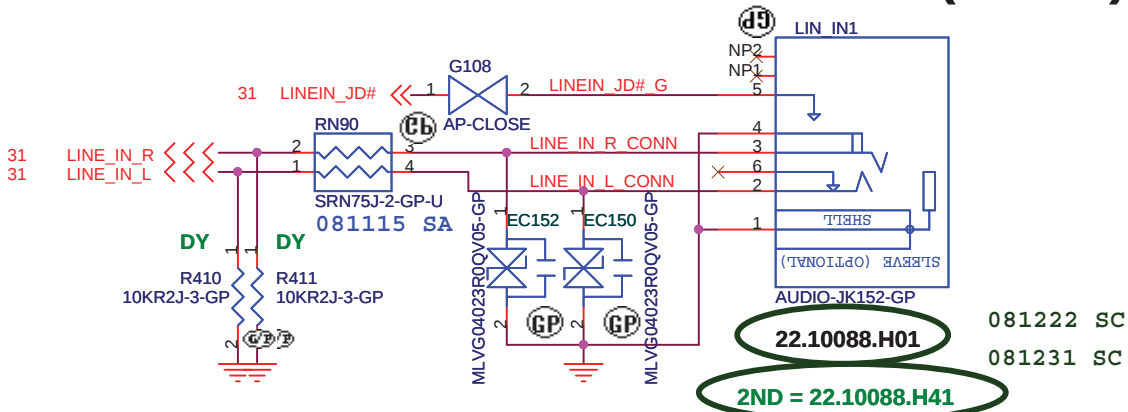
Rev

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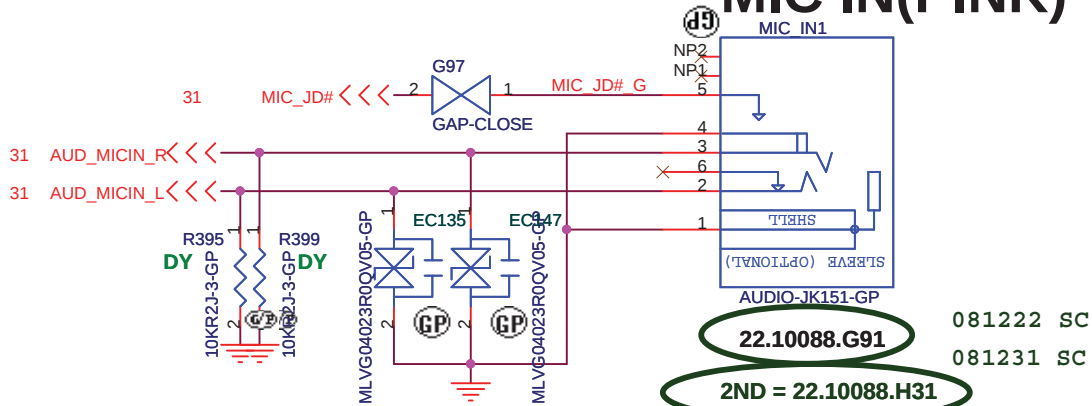
Date: Friday, March 06, 2009

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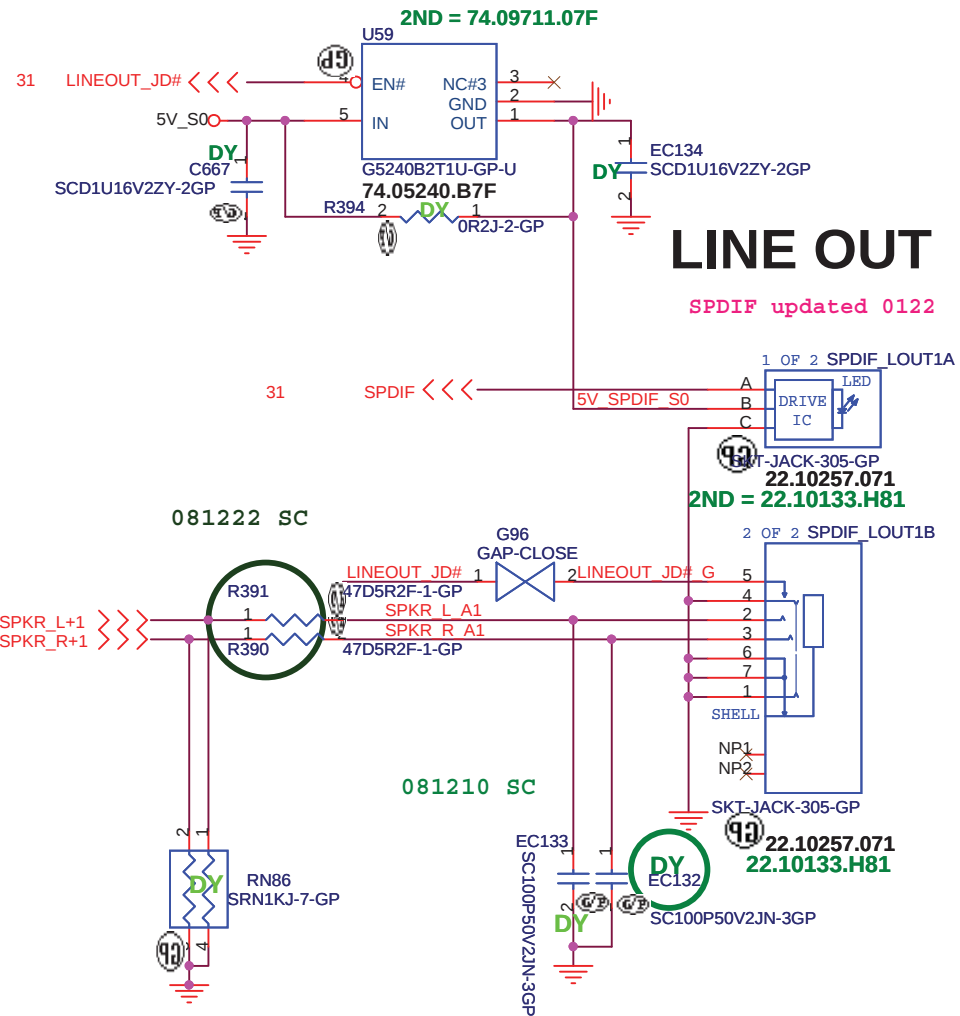
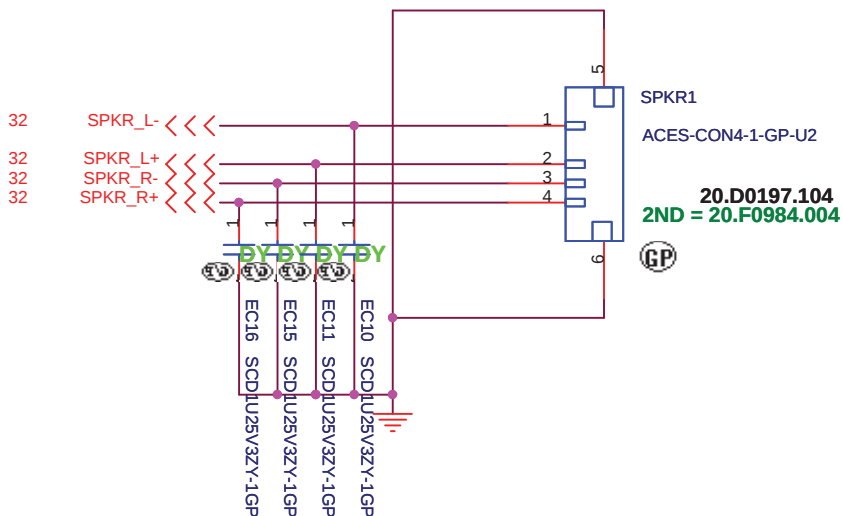
LINE IN(BLUE)



MIC IN(PINK)



REAR Speaker



<Core Design>

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AUDIO JACK

Size
A4

Document Number

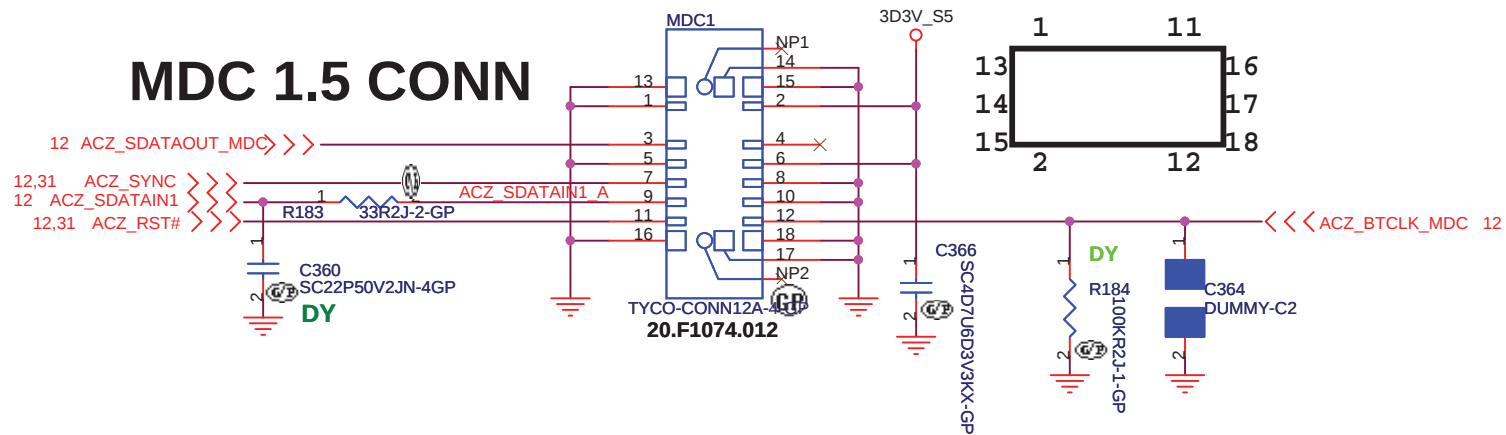
JM70-PU

Rev
-2

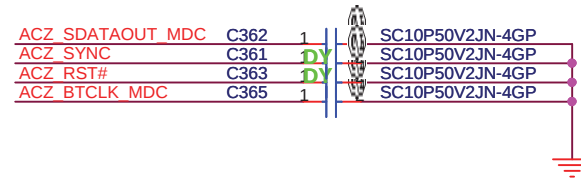
Date: Friday, March 06, 2009

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MDC 1.5 CONN



090211 -1 EMI
Stuff C362,C365 (10P)



<Core Design>

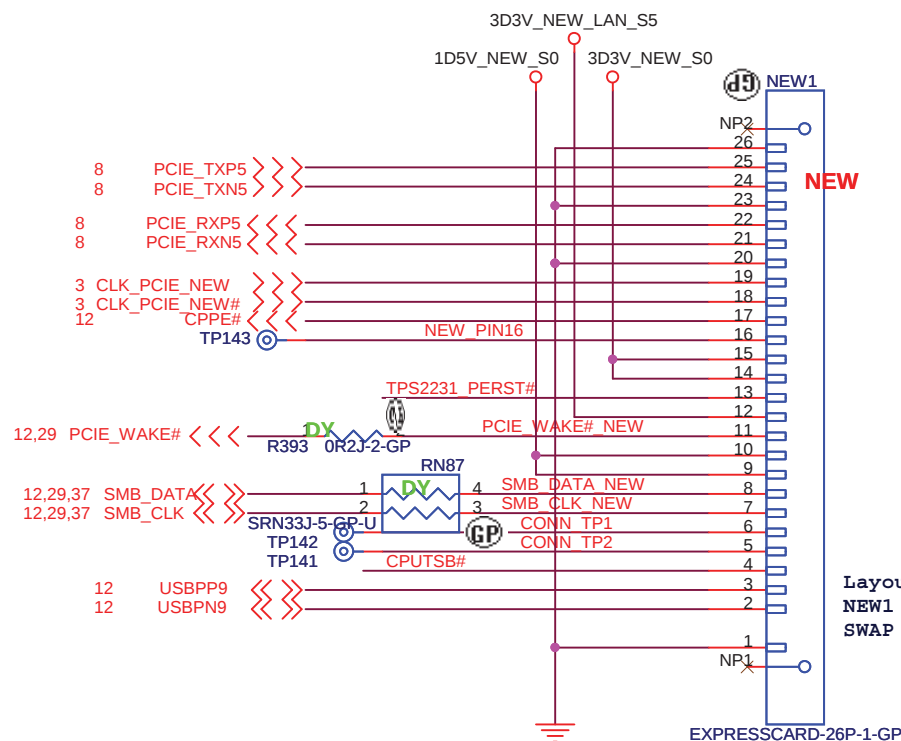
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Title			
MDC			
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090119 -1

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NEWCARD Connector

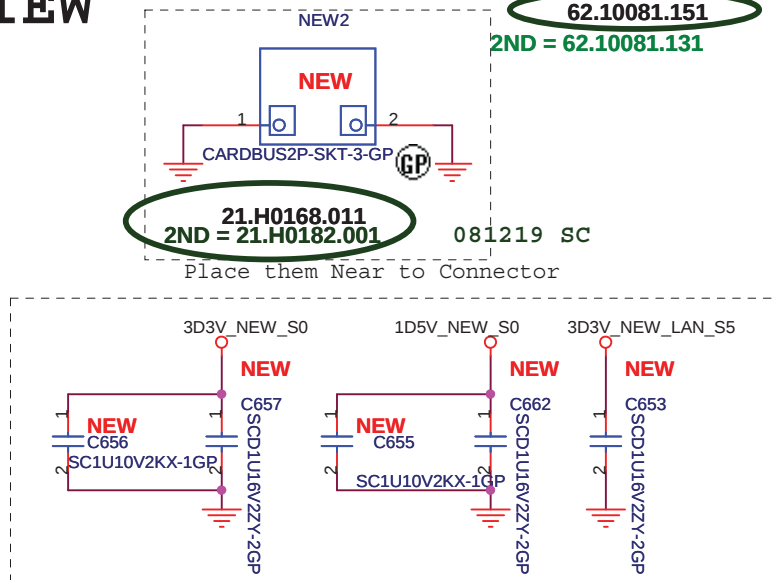
ENG stage without NEW card function 12/22



Layout Request 1226
NEW1 & NEW2
SWAP 1st & 2nd

TOP VIEW

1
26



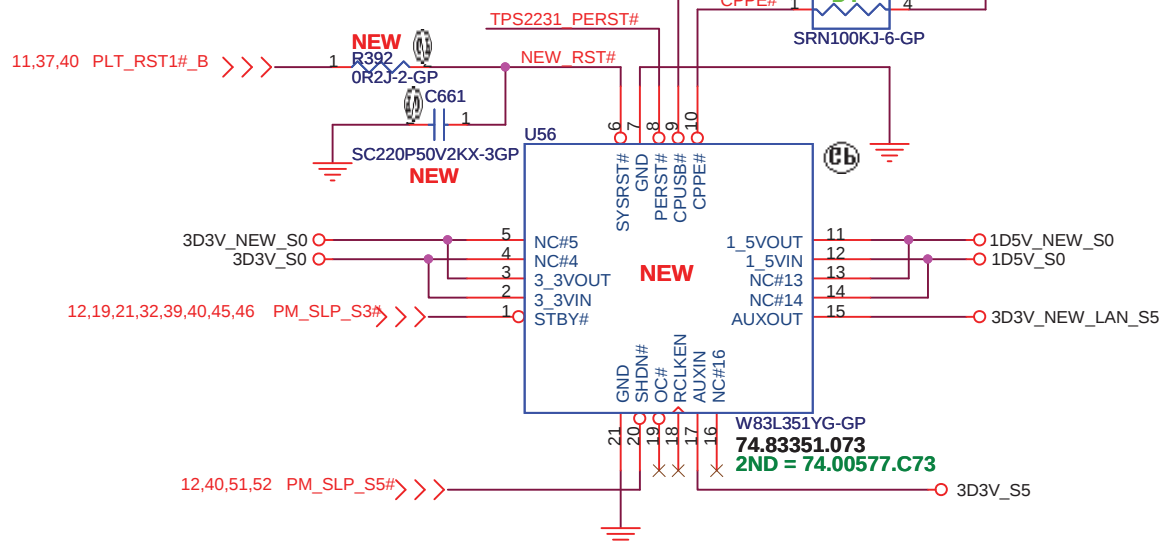
081219 SC

62.10081.151

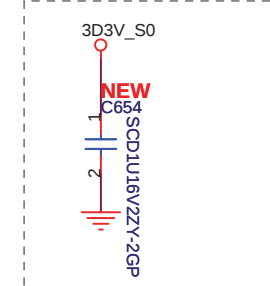
2ND = 62.10081.131

081219 SC

Place them Near to Connector



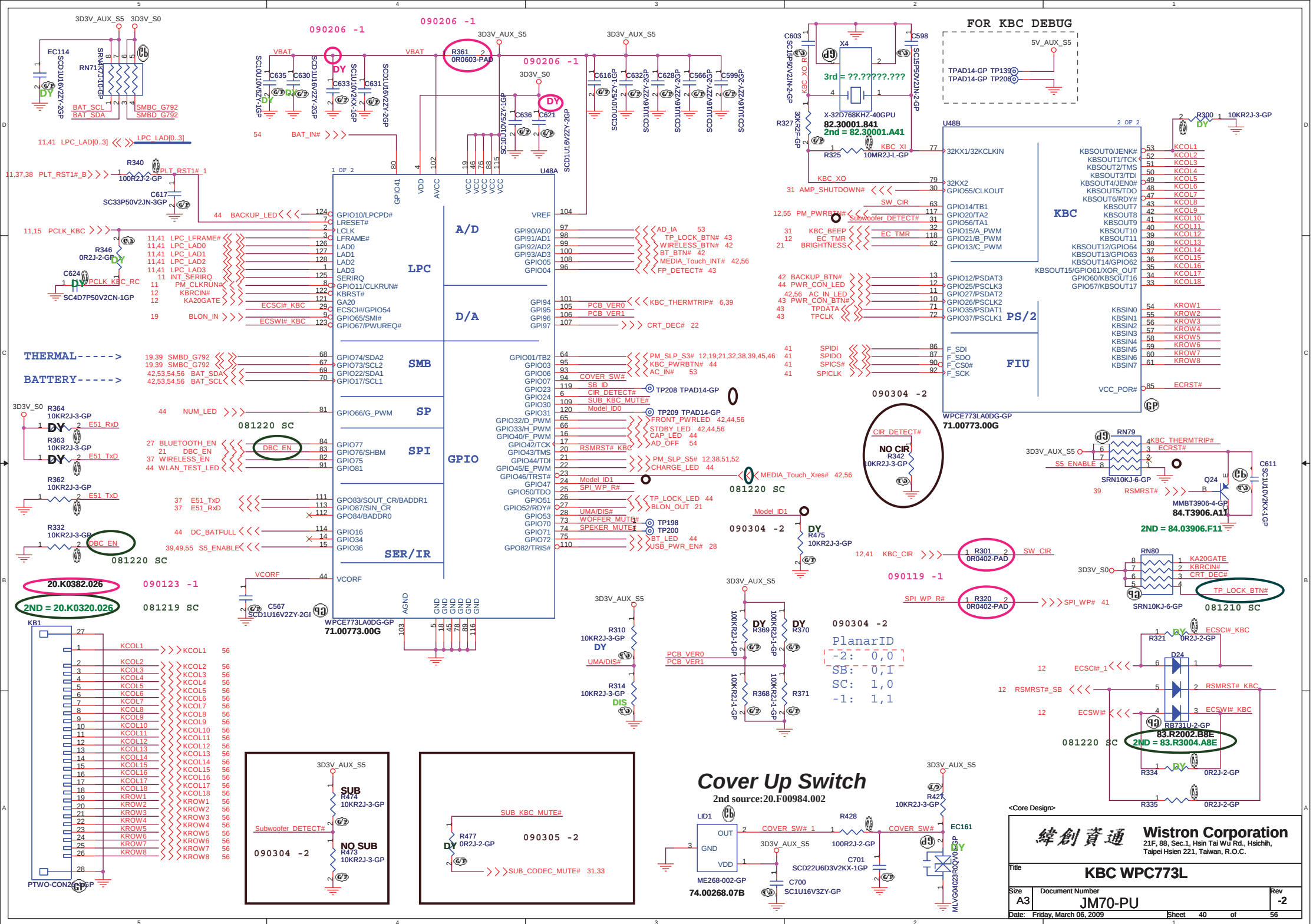
Place them Near to Chip



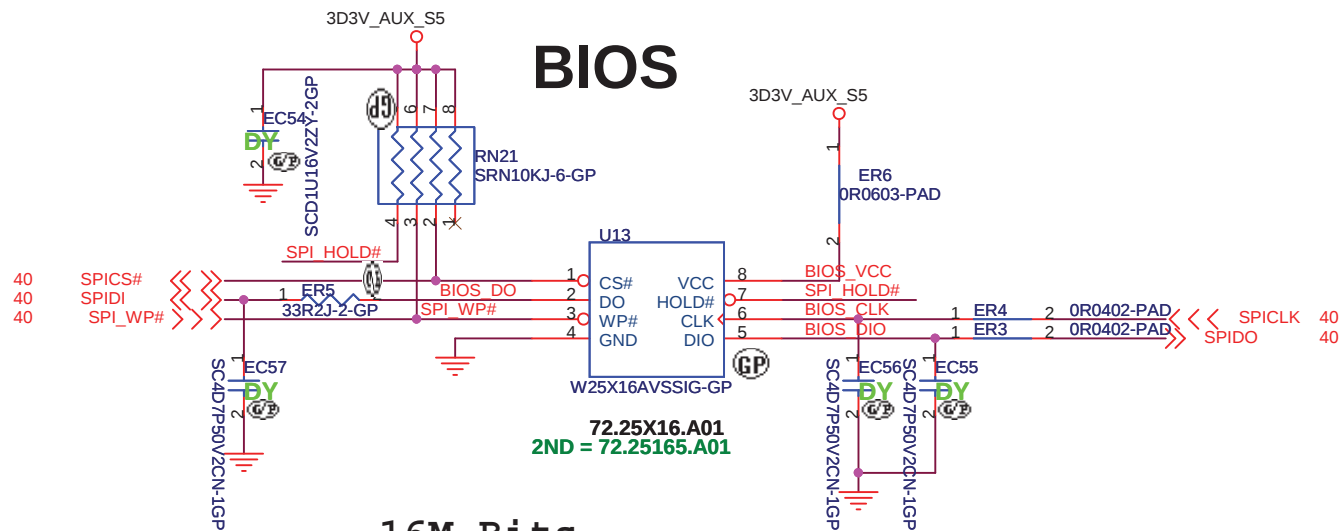
74.00577.C73
new card power switch
GMT cost down solution

<Core Design>

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Title		
NEW CARD		
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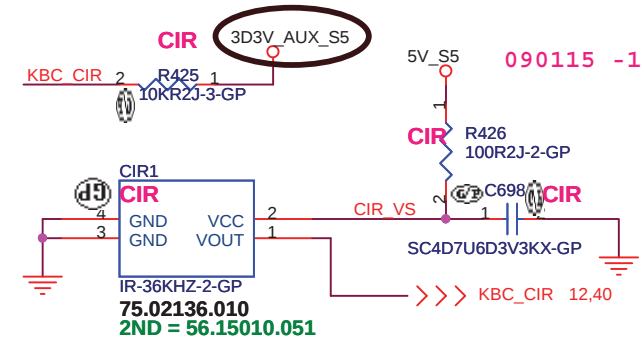
BIOS



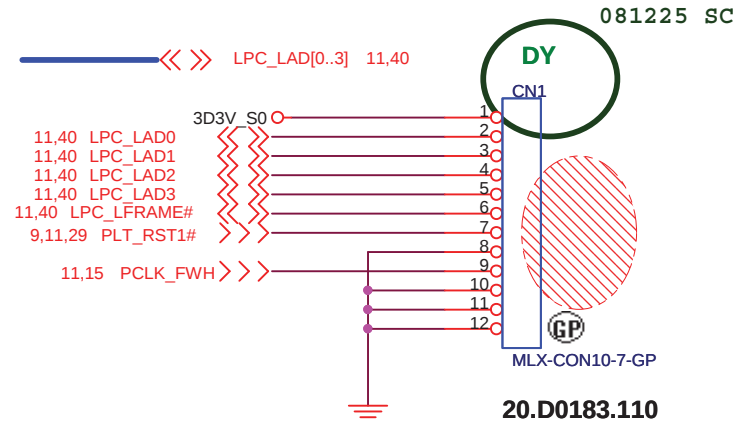
16M Bits

SPI FLASH ROM

CIR Module



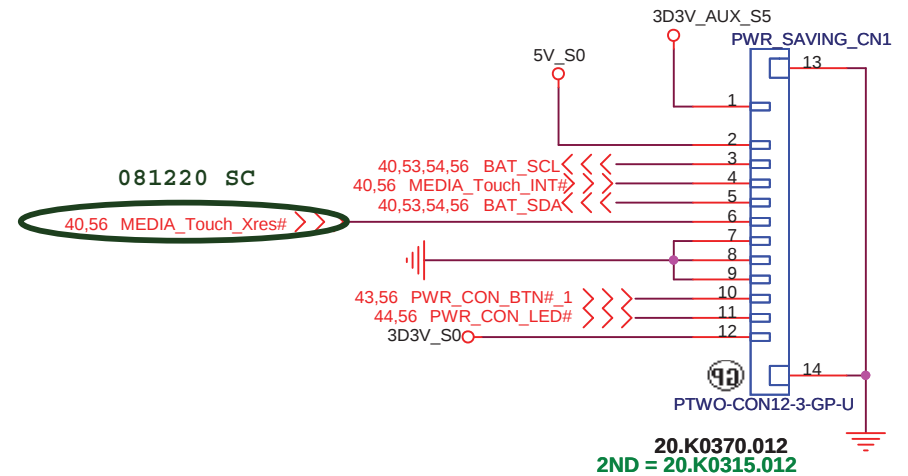
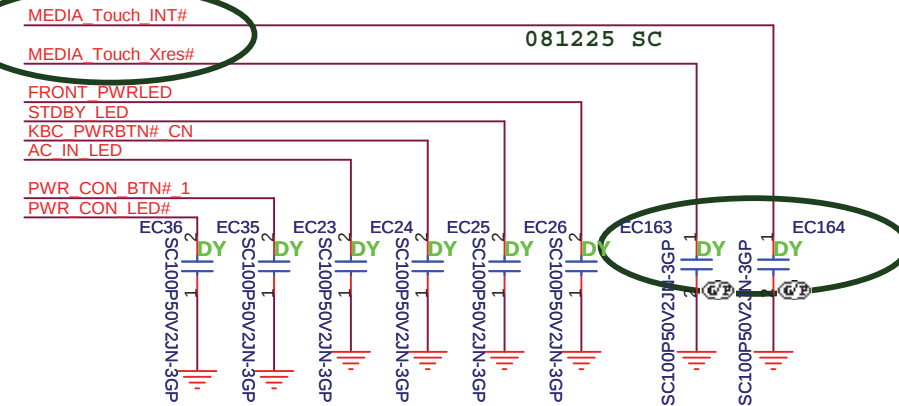
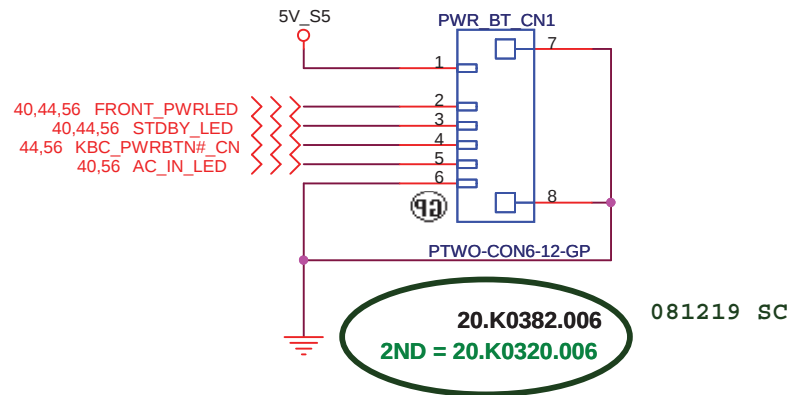
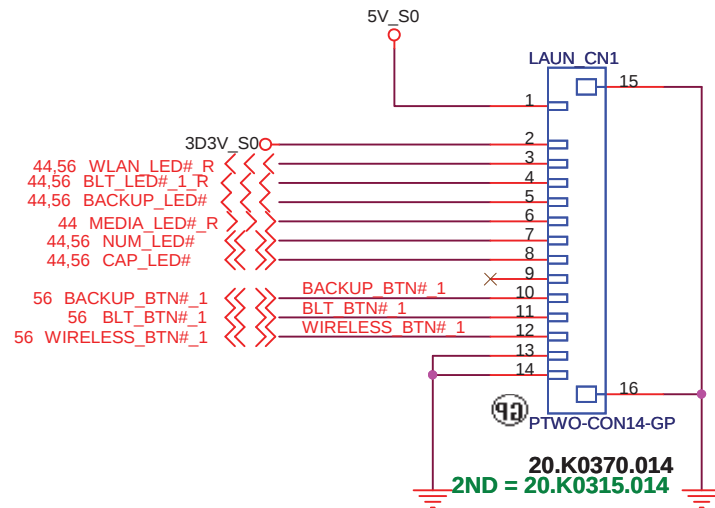
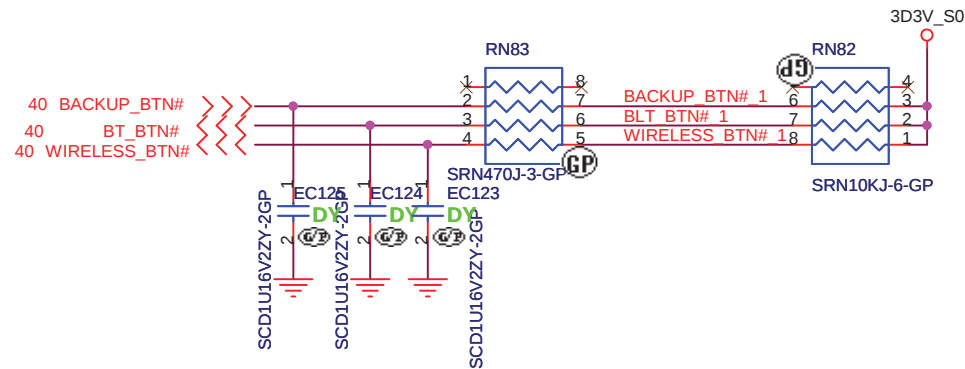
GOLDEN FINGER FOR DEBUG BOARD



<Core Design>

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Title			
BIOS & CIR			
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LAUNCH



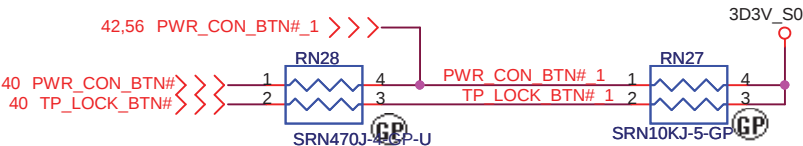
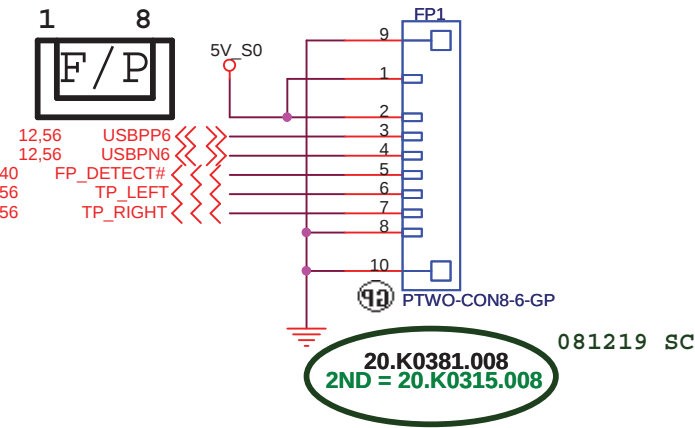
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緯創資通

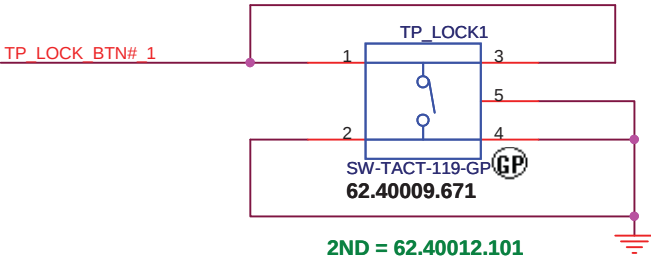
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Taipei Hsien 221, Taiwan, R.O.C.

Title		
LAUNCH & LID		
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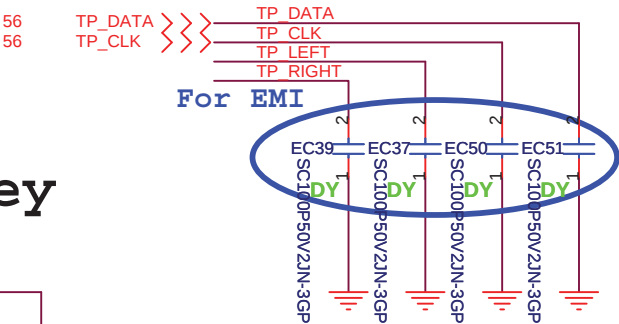
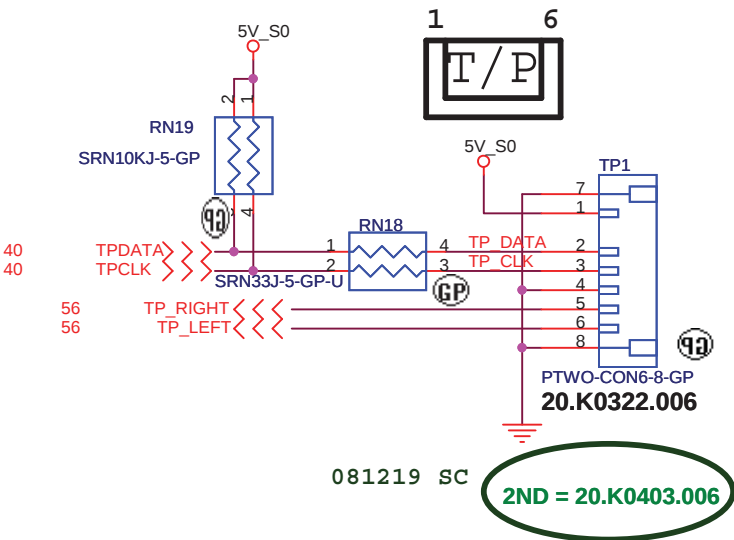
Finger printer



TP_LOCK key



TOUCH PAD

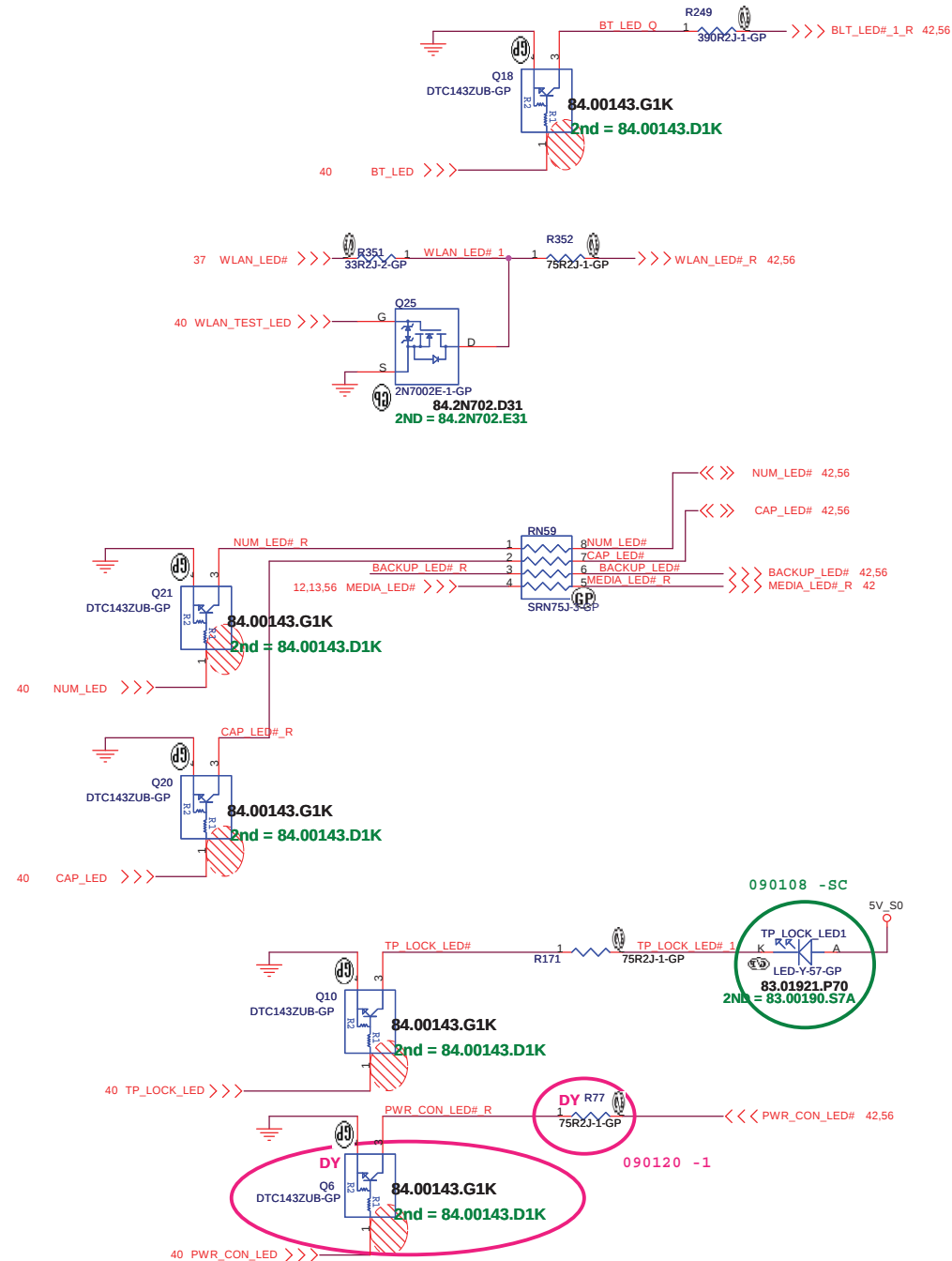
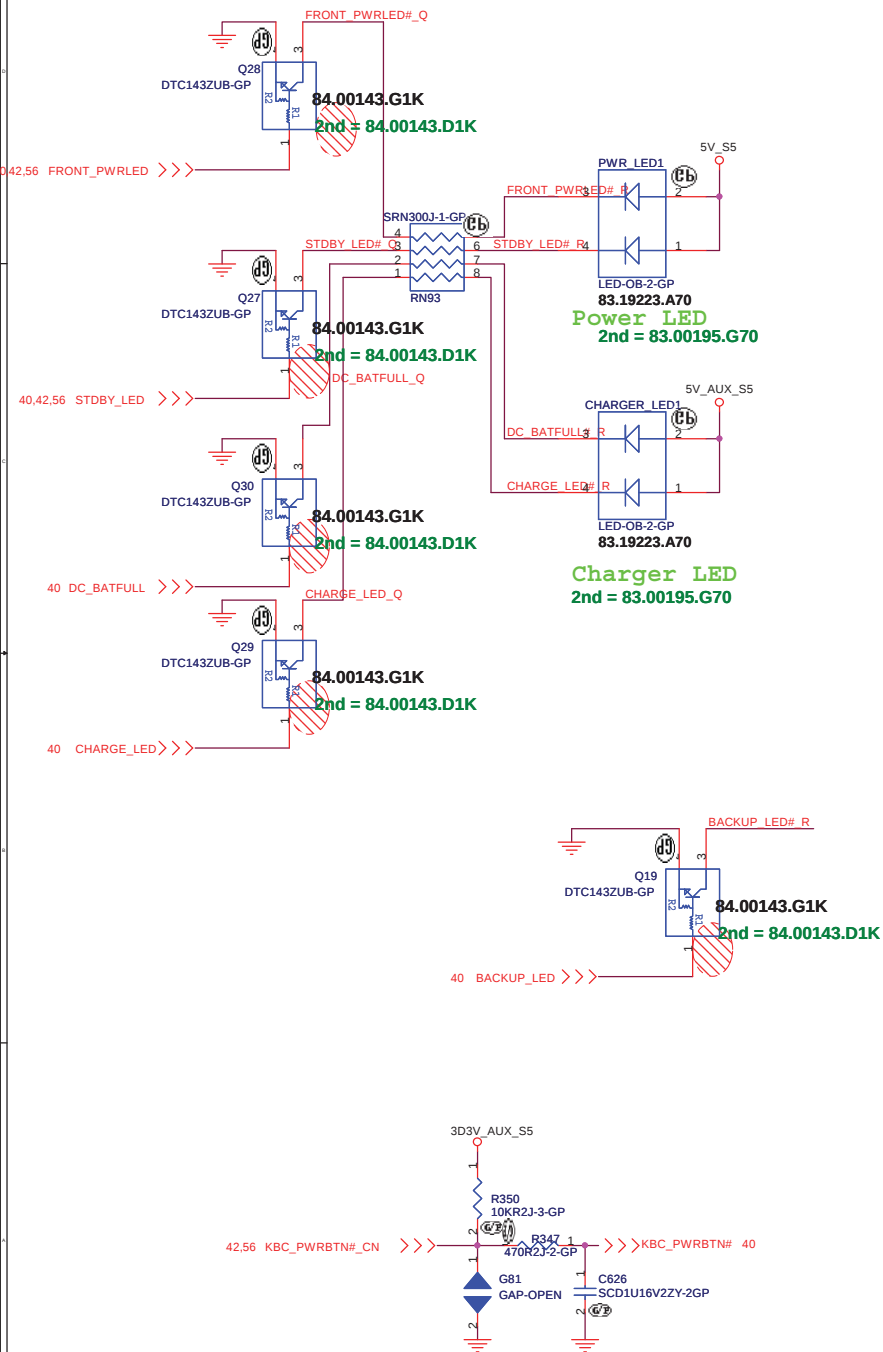


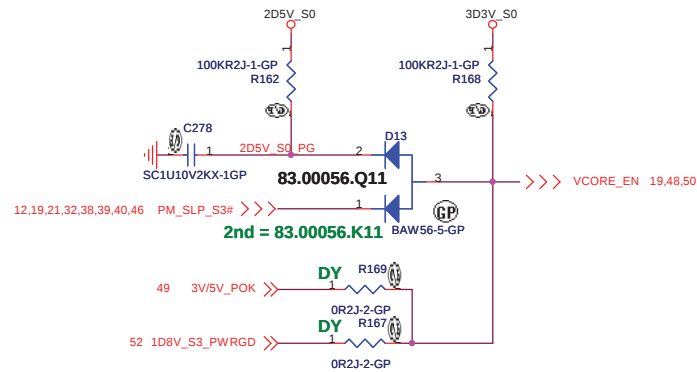
For EMI

<Core Design>

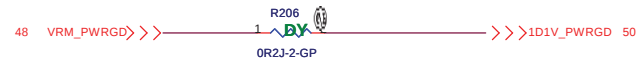
Title		
Finger Printer		
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LED

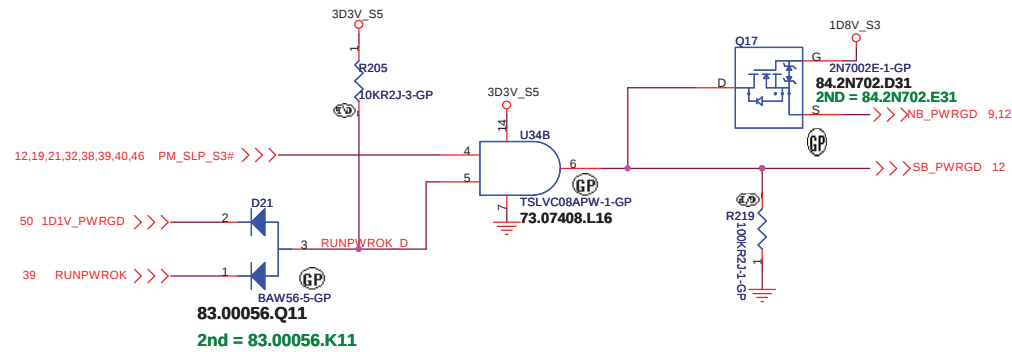




P/H @ 1D8V_S3 PAGE



Reference schematic recommend



<Core Design>

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Title

POWER ON LOGIC

Size
A3

Document Number

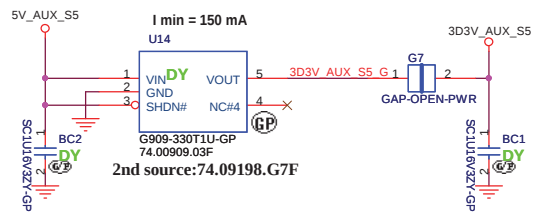
JM70-PU

Date: Friday, March 06, 2009

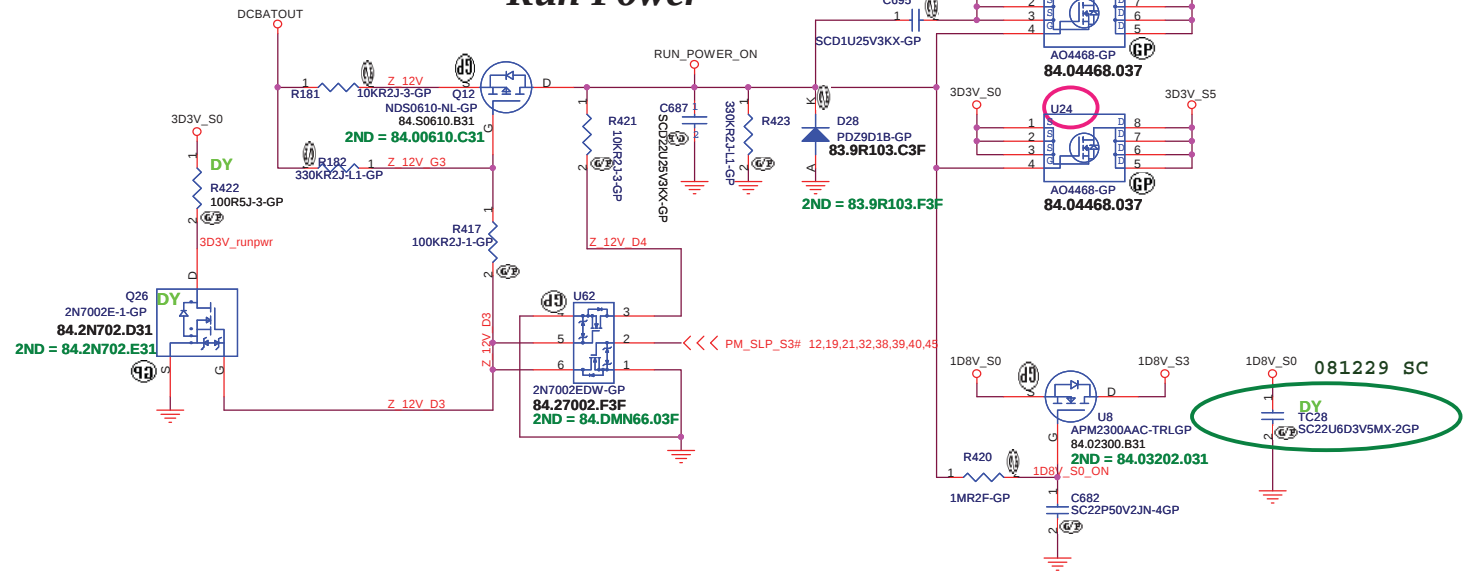
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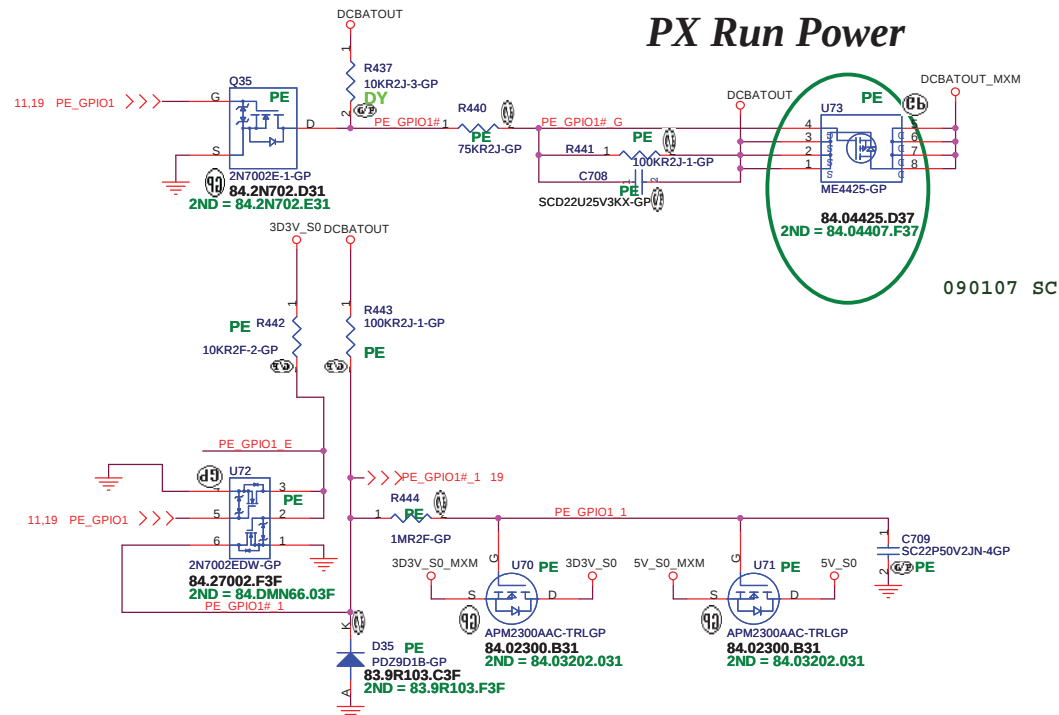
Aux Power 3D3V_AUX_S5



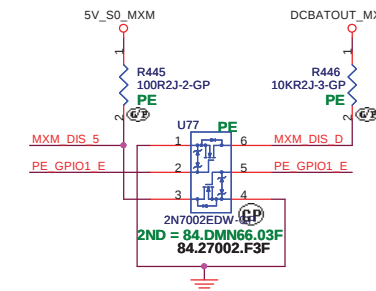
Run Power



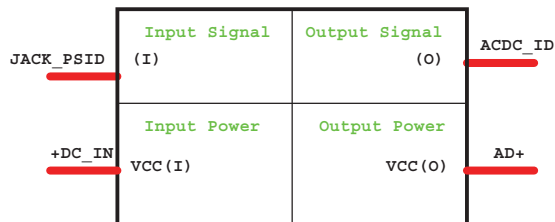
PX Run Power



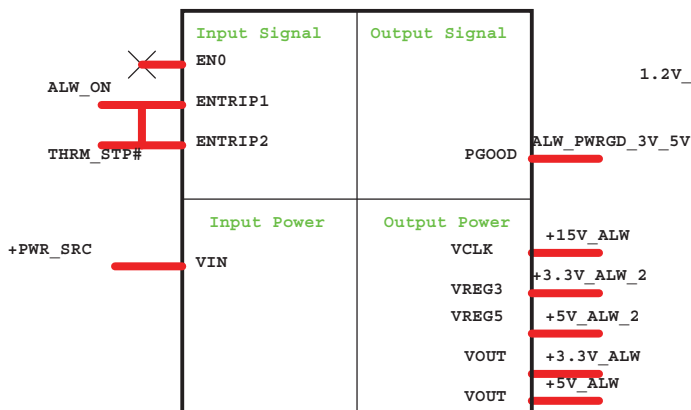
PX Run Power Discharge circuit



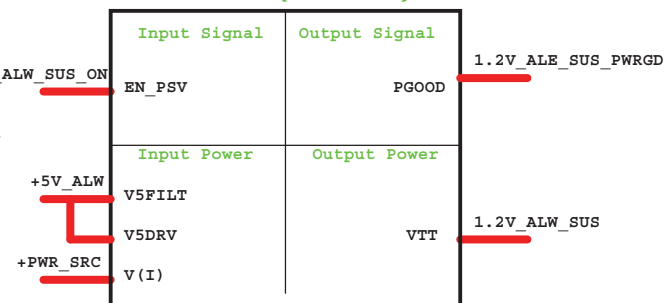
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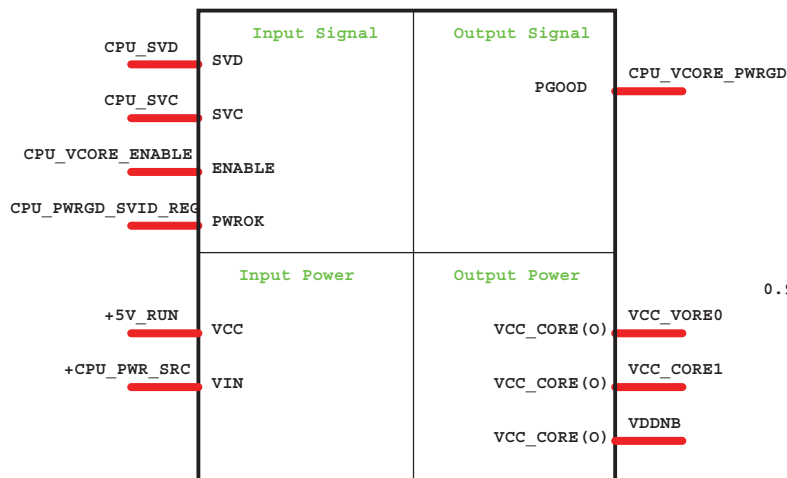
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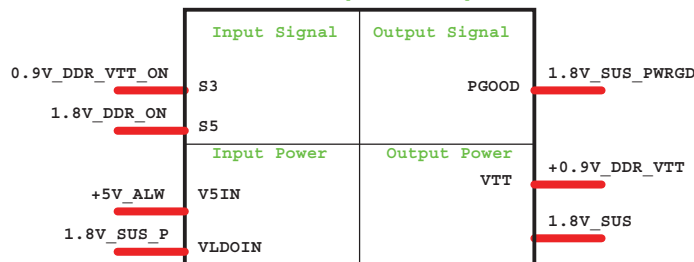
DCDC 1D2V(TPS5117)



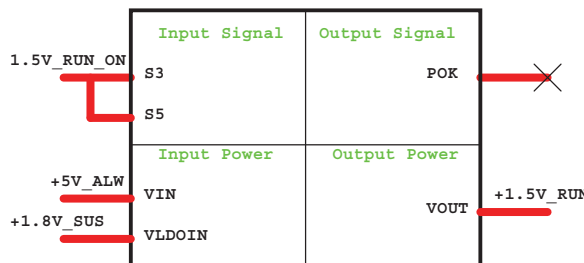
CPU_CORE ISL6265HRTZ



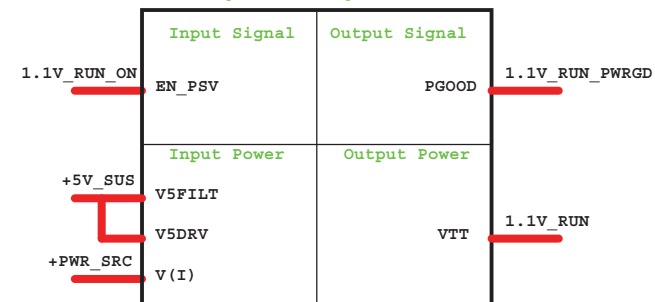
1D8V/0D9V(TPS5116)



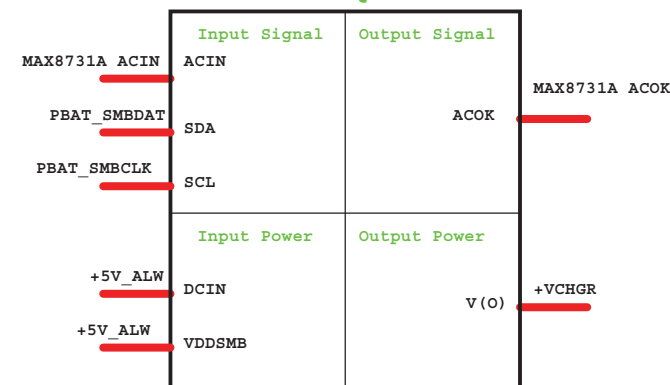
1.5V_LDO



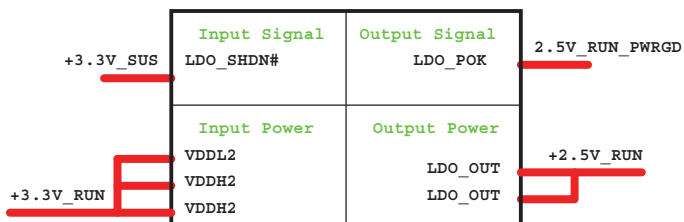
1D1V(TPS5117)



CHARGER BQ24745



2.5V LDO EMC4002

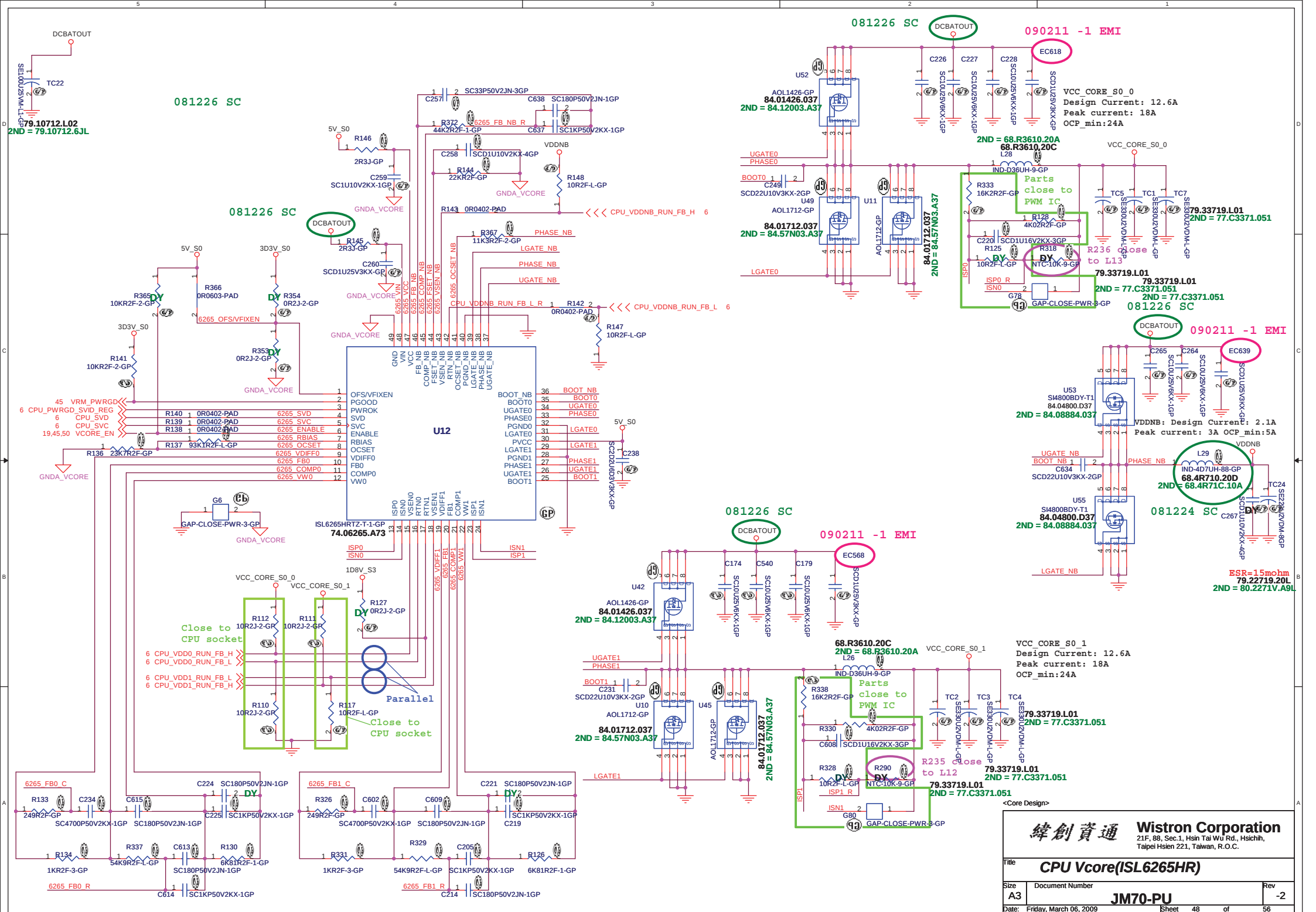


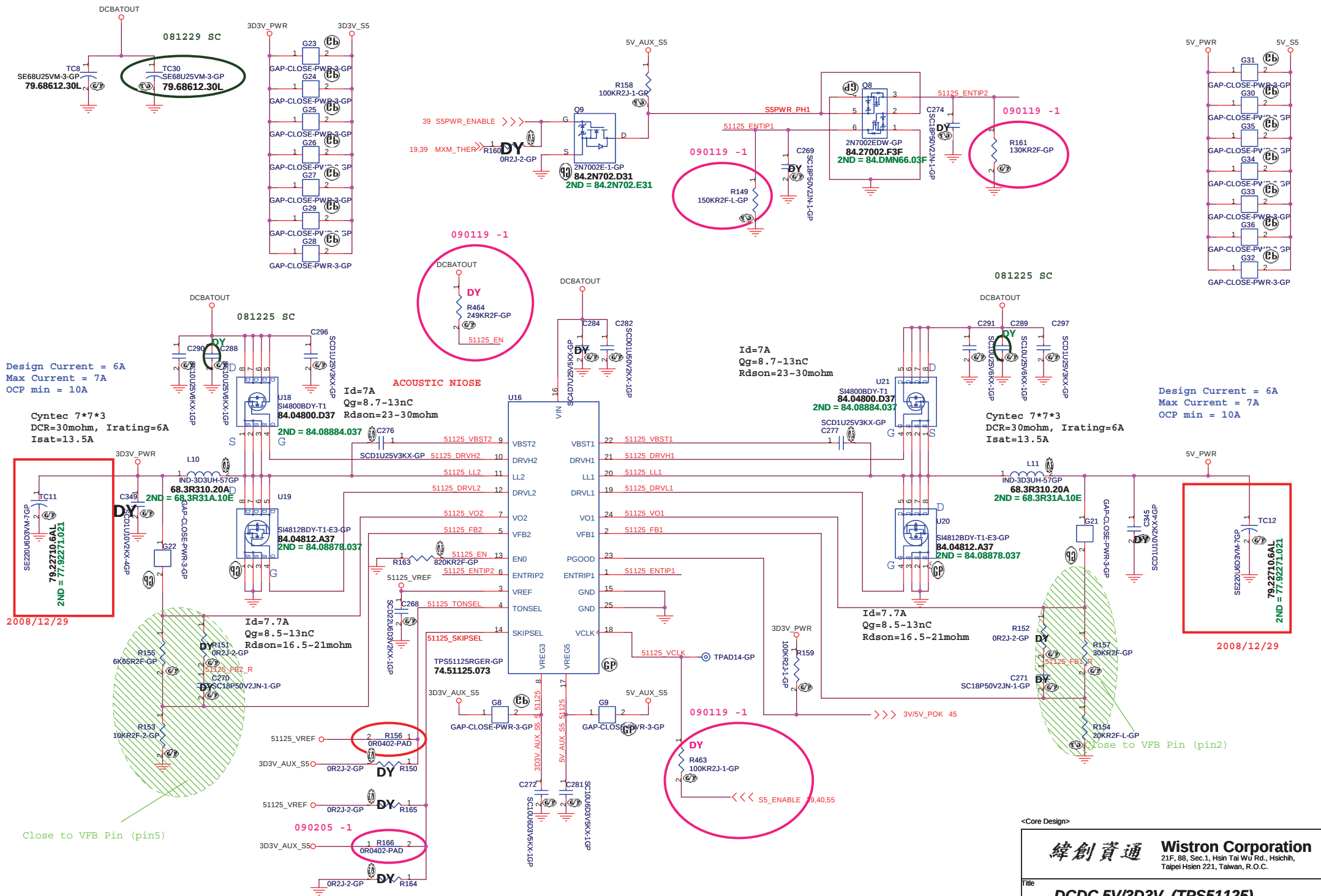
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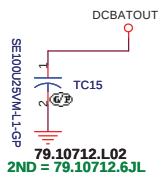
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title Power Block Diagram

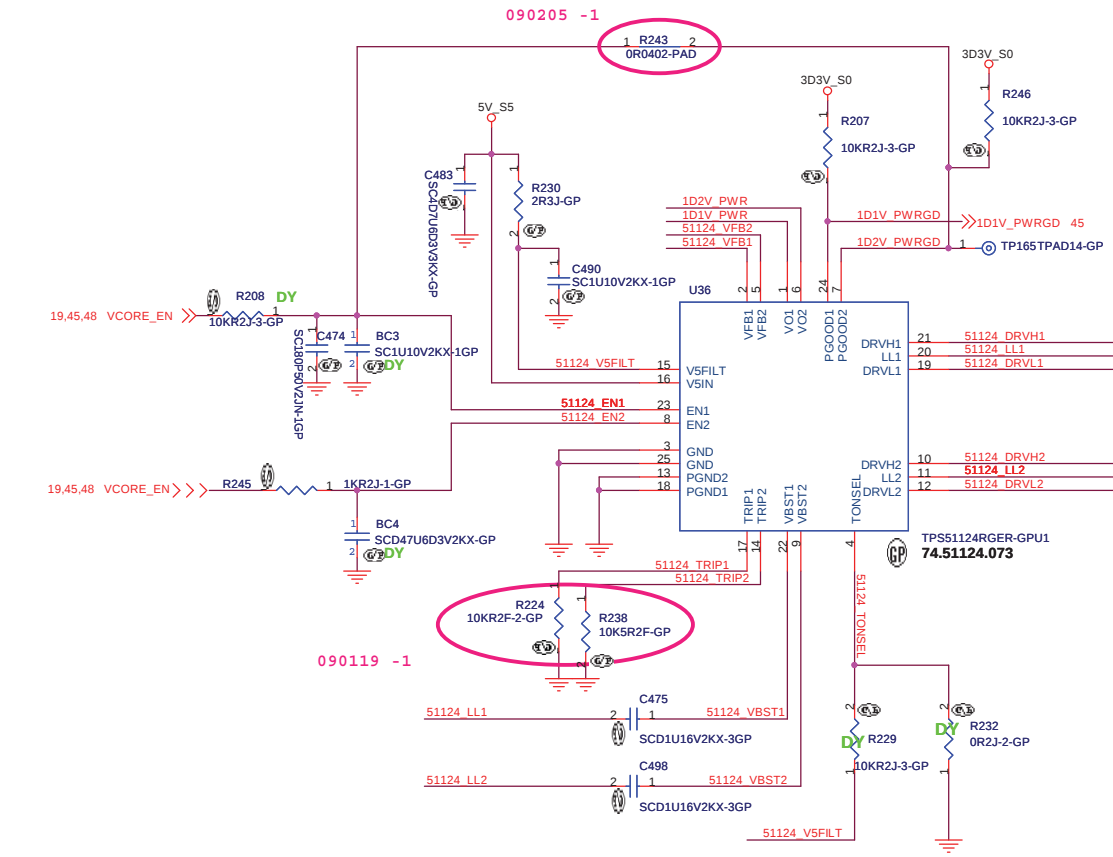
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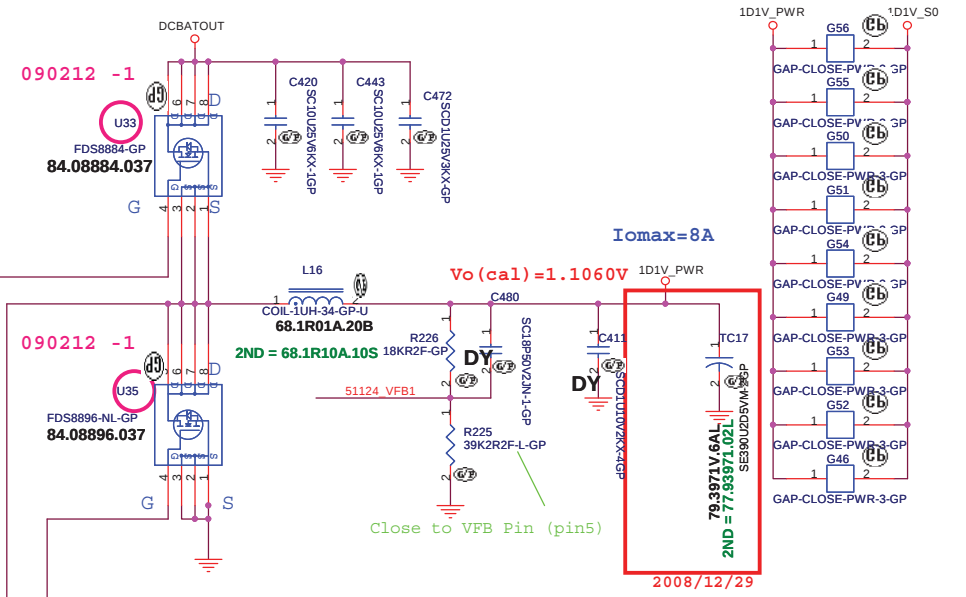


$V_{trip} (mV) = R_{trip} (Kohm) * 10 (uA)$
 $I_{ocp} = (V_{trip} / R_{dson}) + ((1 / (2 * L * f)) * ((V_{in} - V_{out}) * V_{out}) / V_{in})$

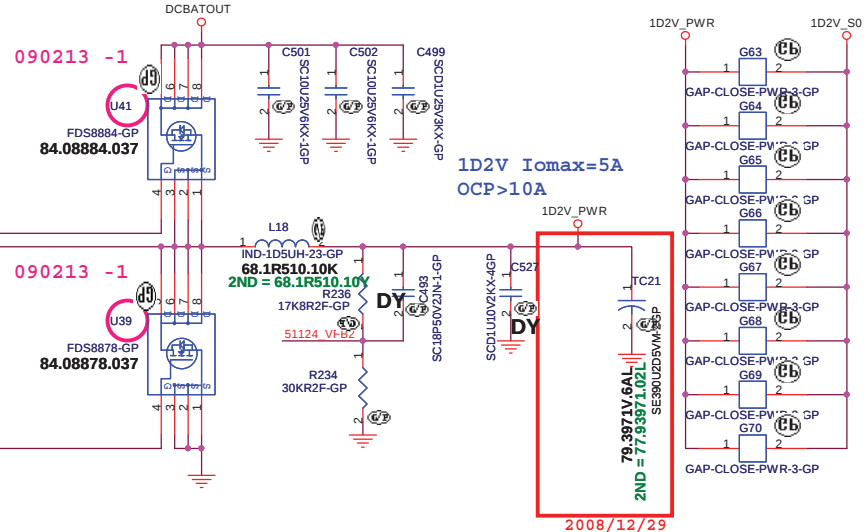


	GND	OPEN	V5FILT
TONSEL	240k/CH1 300k/CH2	300k/CH1 360k/CH2	360k/CH1 420k/CH2

$V_{out} = 0.758V * (R1 + R2) / R2$ --> PWM mode
 $V_{out} = 0.764V * (R1 + R2) / R2$ --> Skip Mode

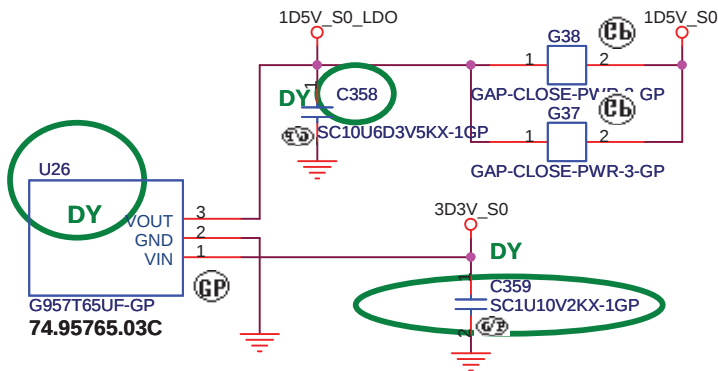


20080307_Modify by
 Brian
 ACOUSTIC NIOSE



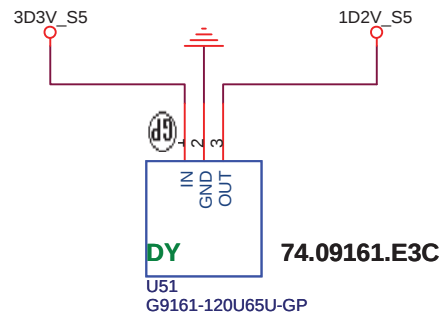
G957

1D5V_S0
Iomax=1A

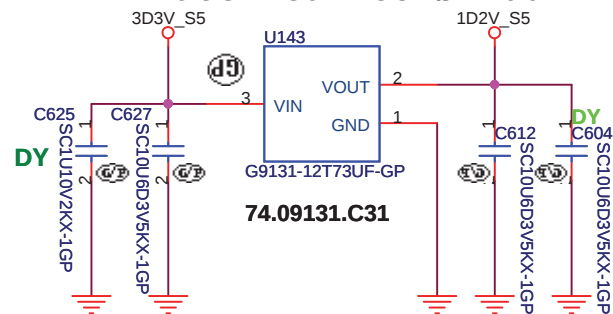


081230 SC

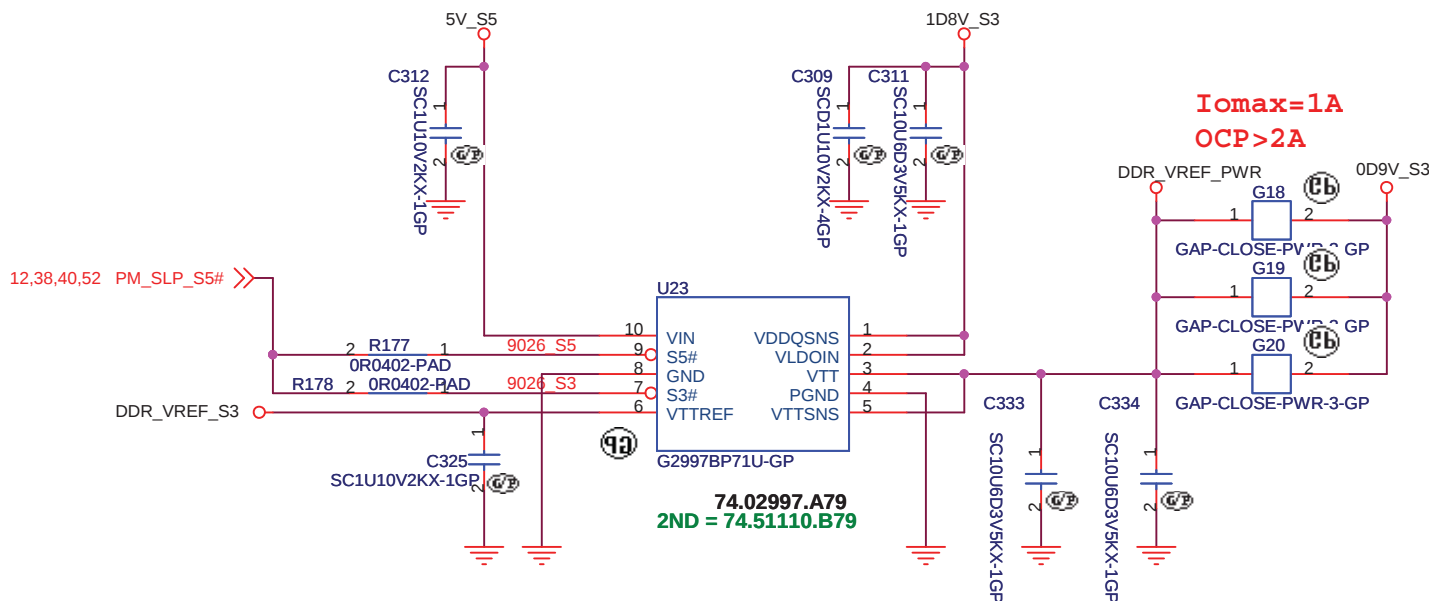
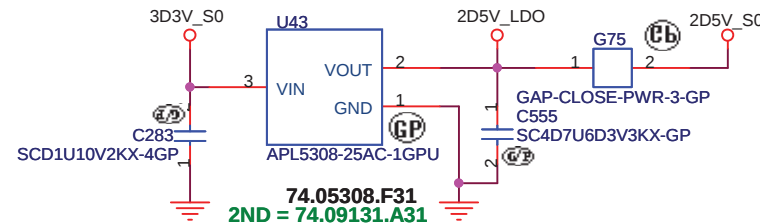
1D2V_S5
Iomax=400mA



Place near to SB700



2D5V_S0
Iomax=0.3A 2D5V/300mA



Iomax=1A
OCP>2A

<Core Design>

緯創資通

Wistron Corporation

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Taipei Hsien 221, Taiwan, R.O.C.

Title

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